

Service Reference





Service Reference

WARNING

The following servicing instructions are for use by qualified service personnel only. To avoid personal injury, do not perform any servicing unless you are qualified to do so. Refer to the Safety Summary prior to performing any service.

Please check for CHANGE INFORMATION at the rear of this manual.



Instrument Serial Numbers

Each instrument manufactured by Tektronix has a serial number on a panel insert or tag, or stamped on the chassis. The first letter in the serial number designates the country of manufacture. The last five digits of the serial number are assigned sequentially and are unique to each instrument. Those manufactured in the United States have six unique digits. The country of manufacture is identified as follows:

B010000 Tektronix, Inc., Beaverton, Oregon, USA
E200000 Tektronix United Kingdom, Ltd., London
J300000 Sony/Tektronix, Japan
Tektronix Holland, NV, Heerenveen, The Netherlands

Instruments manufactured for Tektronix by external vendors outside the United States are assigned a two digit alpha code to identify the country of manufacture (e.g., JP for Japan, HK for Hong Kong, IL for Israel, etc.).

Tektronix, Inc., P.O. Box 500, Beaverton, OR 97077

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Contents

General Information	1-1
Safety Summary	1-2
Terms in Manuals	1-2
Terms on Equipment	1-2
Symbols in Manuals	1-2
Symbols on Equipment	1-2
Power Source	1-2
Grounding the Product	1-2
Danger Arising from Loss of Ground	1-3
Do Not Operate in Explosive Atmospheres	1-3
Do Not Service Alone	1-3
Use Care When Servicing with Power On	1-3
Installing and Removing an Amplifier	1-3
Instrument Options	1-5
Packaging for Shipment	1-5
Operating Environment	1-6
Checks And Adjustments	2-1
	2-3
	2-5
	2-6
	2-6
	2-6
	2-7
	2-7
	2-7
Procedure 3 Step Response/ Bandwidth	2-9
	2-9
Measurement Limits	2-9
	2-9
· · · · · · · · · · · · · · · · · · ·	2-10
· · · · · · · · · · · · · · · · · · ·	2-13
· · · · · · · · · · · · · · · · · · ·	2-13
	2-13
·	2-13
·	2-15
·	2-15
	2-15
	2-17
· · · · · · · · · · · · · · · · · · ·	2-17
	2-17
	2-17
	2-20
	2-20
	2-20
	2-20

Specification 2-23	Section 2 Checks and Adjustments (cont.)	
Setup to Check DC Balance 2-23 Procedure of Internal Trigger 2-25 Specification 2-25 Setup to Check the Internal Trigger 2-25 Procedure 10 External Trigger 2-25 Procedure 10 External Trigger 2-26 Specification 2-26 Setup to Check the External Trigger 2-26 Setup to Check External Trigger 2-26 Procedure to Check External Trigger 2-26 Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Self Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6	Procedure 8 DC Balance	2-23
Procedure to Check DC Balance 2-23 Procedure 9 Internal Trigger 2-25 Specification 2-25 Setup to Check the Internal Trigger 2-25 Procedure 10 External Trigger 2-25 Procedure 10 External Trigger 2-26 Specification 2-26 Specification 2-26 Setup to Check the External Trigger 2-26 Setup to Check the External Trigger 2-26 Setup to Check External Trigger 2-26 Procedure to Check External Trigger 2-26 Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-3 Self Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Restoring Calibration Data 3-6 Restoring Calibration Data 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of FRU Names 3-8 Abbreviations of FRU Names 3-8 Error Index Codes 3-9 Decoding an S/H Fallure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the Front Panel Board 3-20 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the Presampler Heat Sink 3-22 Removing/Replacing the Presampler Heat Sink 3-23 Removing/Replacing the Presampler Heat Sink 3-23 Removing/Replacing t	Specification	-
Procedure 9 Internal Trigger 2-25 Specification 2-25 Setup to Check the Internal Trigger 2-25 Procedure 10 External Trigger 2-25 Specification 2-26 Setup to Check the External Trigger 2-26 Setup to Check External Trigger 2-26 Procedure to Check External Trigger 2-26 Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostic Troubleshooting 3-3 Diagnostic Troubleshooting 3-3 Self Tests 3-3 Error Index Codes 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Abbreviations of FRU Names 3-8<	Setup to Check DC Balance	
Specification 2-25 Setup to Check the Internal Trigger 2-25 Procedure to Check Internal Trigger 2-26 Procedure 10 External Trigger 2-26 Sepcification 2-26 Setup to Check the External Trigger 2-26 Procedure to Check External Trigger 2-26 Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names	Procedure to Check DC Balance	
Setup to Check the Internal Trigger 2-25 Procedure to Check Internal Trigger 2-25 Procedure 10 External Trigger 2-26 Specification 2-26 Specification 2-26 Setup to Check the External Trigger 2-26 Procedure to Check External Trigger 2-26 Procedure to Check External Trigger 2-26 Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Self Tests 3-3 Self Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-22 Removing/Replacing the BNC Connector Assemblies 3-23 Removing/Replacing the BNC Connector Assemblies 3-23 Removing/Replacing the BNC Pront Panel Board 3-25 Removing/Replacing the BNC Pront Panel Board 3-25 Removing/Replacing the BNC Pront Panel Board 3-25 Removing/Replacing the BNC Connector Assemblies 3-25 Removing/Replacing the BNC Pront Panel Board 3-25 Removing/Replacing the BNC Pront Panel Source Board 3-25 Removing/Replacing the BNC Pront Panel Source Board 3-25 Removing/Replacing the Fo	Procedure 9 Internal Trigger	
Procedure to Check Internal Trigger	Specification	
Procedure 10 External Trigger 2-26		
Specification 2-26 Setup to Check the External Trigger 2-26 Procedure to Check External Trigger 2-26 Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostic Soverview 3-3 Kernel Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 <td>Procedure to Check Internal Trigger</td> <td></td>	Procedure to Check Internal Trigger	
Setup to Check the External Trigger 2-26 Procedure to Check External Trigger 2-26 Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostic Overview 3-3 Kernel Tests 3-3 Self Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-8 Abbreviations of FRU Names 3-8 Abbreviations of FRU Names 3-8 Abbreviations of FRU Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Corrective Maintenance 3-12 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Procedure 10 External Trigger	
Maintenance	Specification	
Maintenance 3-1 Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-25 Removing/Replacing the RMS Pickoff board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33		
Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the BNC Connector Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the Presampler Heat Sink 3-25 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Procedure to Check External Trigger	2-26
Preventive Maintenance 3-1 Amplifier Shield Removal 3-1 Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the BNC Connector Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the Presampler Heat Sink 3-25 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33		
Ampliffer Shield Removal Cleaning Cleaning S-1 Visual Inspection Periodic Electrical Adjustment Jiagnostic Troubleshooting Jiagnostic Troubleshooting Jiagnostics Overview S-3 Kernel Tests Self Tests/Extended Diagnostics Self Tests Self Tests/Extended Diagnostics Self Tests/Extended Diagnostics Self Tests Self Tests/Extended Diagnostics Self Tests Self Tests Self Tests Self Tests Self Tests Self Tests/Extended Diagnostics Self Tests		• •
Cleaning 3-1 Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostic Soverview 3-3 Kernel Tests 3-3 Kernel Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Corrective Maintenance 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33		•
Visual Inspection 3-2 Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Error Index Codes 3-5 Error Index Codes 3-6 Enhanced Accuracy Errors 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Corrective Maintenance 3-12 Corrective Maintenance 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the A2 Front Panel Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Presampler Heat Sink 3-25 Removing/Replacing the Presampler Heat Sink 3-25 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Amplifier Shield Removal	
Periodic Electrical Adjustment 3-2 Diagnostic Troubleshooting 3-3 Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Faillure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Corrective Maintenance 3-12 Corrective Maintenance 3-12 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Cleaning	
Diagnostics Troubleshooting	Visual Inspection	
Diagnostics Overview 3-3 Kernel Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the Front Panel Assembly 3-14 Removing/Replacing the Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Periodic Electrical Adjustment	
Kernel Tests 3-3 Self Tests 3-5 Error Index Codes 3-5 Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Corrective Maintenance 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing the Presampler Heat Sink 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Diagnostic Troubleshooting	
Self Tests	Diagnostics Overview	
Error Index Codes Using the Self Tests/Extended Diagnostics Enhanced Accuracy Errors Calibrating a New Configuration Restoring Calibration Data Memory Backup Power for the Amplifier Field Replaceable Unit (FRU) Guide Abbreviations of FRU Names Abbreviations of Component and Module Names Error Index Codes Decoding an S/H Failure Fuse Troubleshooting Jumpers Corrective Maintenance Ordering Parts Static-Sensitive Device Classification Removing/Replacing the Front Panel Assembly Removing/Replacing the RMS Pickoff board Removing/Replacing the RMS Pickoff board Removing/Replacing the RMS Pickoff board Removing/Replacing the A1 Main Board Removing/Replacing the Presampler Heat Sink Removing/Replacing the Presampler Heat Sink Removing/Replacing the Presampler Heat Sink Removing/Replacing Hypcon Assemblies Removing/Replacing the Presampler Heat Sink Removing/Replacing the Presampler Heat Sink Removing/Replacing Hypcon Assemblies Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33		
Using the Self Tests/Extended Diagnostics 3-6 Enhanced Accuracy Errors 3-6 Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-20 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Self Tests	
Enhanced Accuracy Errors	Error Index Codes	
Enhanced Accuracy Errors Calibrating a New Configuration Restoring Calibration Data Memory Backup Power for the Amplifier Field Replaceable Unit (FRU) Guide Abbreviations of FRU Names Abbreviations of Component and Module Names Error Index Codes Decoding an S/H Failure Fuse Troubleshooting Jumpers Corrective Maintenance Ordering Parts Static-Sensitive Device Classification Removing/Replacing the Front Panel Assembly Removing/Replacing the ENC Connector Assemblies Removing/Replacing the RMS Pickoff board Removing/Replacing the RMS Pickoff board Removing/Replacing the A1 Main Board Removing/Replacing the Presampler Heat Sink Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Using the Self Tests/Extended Diagnostics	
Calibrating a New Configuration 3-6 Restoring Calibration Data 3-6 Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Enhanced Accuracy Errors	3-6
Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Calibrating a New Configuration	3-6
Memory Backup Power for the Amplifier 3-7 Field Replaceable Unit (FRU) Guide 3-8 Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Restoring Calibration Data	
Abbreviations of FRU Names Abbreviations of Component and Module Names Error Index Codes Decoding an S/H Failure Jumpers Corrective Maintenance Ordering Parts Static-Sensitive Device Classification Removing/Replacing the Front Panel Assembly Removing/Replacing the A2 Front Panel Board Removing/Replacing the BNC Connector Assemblies Removing/Replacing the RMS Pickoff board Removing/Replacing the RMS Pickoff board Removing/Replacing the A1 Main Board Removing/Replacing the Presampler Heat Sink Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Memory Backup Power for the Amplifier	
Abbreviations of FRU Names 3-8 Abbreviations of Component and Module Names 3-8 Error Index Codes 3-9 Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Field Replaceable Unit (FRU) Guide	
Error Index Codes Decoding an S/H Failure S-10 Fuse Troubleshooting Jumpers 3-12 Jumpers 3-12 Corrective Maintenance Ordering Parts Static-Sensitive Device Classification Removing/Replacing FRUs Removing/Replacing the Front Panel Assembly Removing/Replacing the A2 Front Panel Board Removing/Replacing the BNC Connector Assemblies Removing/Replacing the Cal Relay Removing/Replacing the RMS Pickoff board Removing/Replacing an Attenuator Removing/Replacing the A1 Main Board Removing/Replacing the Presampler Heat Sink Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33		
Decoding an S/H Failure 3-10 Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Abbreviations of Component and Module Names	
Decoding an S/H Failure	Error Index Codes	3-9
Fuse Troubleshooting 3-12 Jumpers 3-12 Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Decoding an S/H Failure	3-10
Jumpers	Fuse Troubleshooting	_
Corrective Maintenance 3-12 Ordering Parts 3-12 Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33		
Ordering Parts	Corrective Maintenance	
Static-Sensitive Device Classification 3-12 Removing/Replacing FRUs 3-14 Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Ordering Parts	
Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33		3-12
Removing/Replacing the Front Panel Assembly 3-17 Removing/Replacing the A2 Front Panel Board 3-20 Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Removing/Replacing FRUs	•
Removing/Replacing the BNC Connector Assemblies 3-21 Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Removing/Replacing the Front Panel Assembly	-
Removing/Replacing the Cal Relay 3-22 Removing/Replacing the RMS Pickoff board 3-23 Removing/Replacing an Attenuator 3-23 Removing/Replacing the A1 Main Board 3-25 Removing/Replacing the Presampler Heat Sink 3-27 Removing/Replacing Hypcon Assemblies 3-29 Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Removing/Replacing the A2 Front Panel Board	
Removing/Replacing the RMS Pickoff board	Removing/Replacing the BNC Connector Assemblies	
Removing/Replacing an Attenuator	Removing/Replacing the Cal Relay	
Removing/Replacing an Attenuator	Removing/Replacing the RMS Pickoff board	
Removing/Replacing the A1 Main Board	Removing/Replacing an Attenuator	
Removing/Replacing the Presampler Heat Sink	Removing/Replacing the A1 Main Board	
Removing/Replacing Hypcon Assemblies	Removing/Replacing the Presampler Heat Sink	
Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-33	Removing/Replacing Hypcon Assemblies	
	Removing/Replacing the Serial Data Interface (SDI) IC (U1540)	3-33
		3-34

Maintenance (cont.)	
Removing/Replacing the EPROM IC	3-35
Programming the Unit Identification and the Calibration Constants	3-36
Multi-Pin Connectors	3-38
Theory of Operation	4-1
System Functional Overview	4-1
Attenuator Assembly Block	4-1
Input Protection Block	4-1
Presampler Block	4-1
Front Panel Control Block	4-2
Kernel Block	4-2
External Trigger Block	4-2
Typical Signal Processing Cycle	4-3
Detailed Block Diagram Descriptions	4-4
Cal Relay	4-4
RMS Overload Detect	4-5
Attenuator Block	4-5
A1 Main Board	4-5
A2 Front Panel Board	4-6
ALTIGICI GIOLDOGICA	•
Replaceable Parts	5-1
Parts Ordering Information	5-1
Module Replacement	5-1
Using the Replaceable Parts List	5-2
Item Names	5-2
Indentation System	5-2
Abbreviations	5-2
Appleviations	0.

Change Information

List of Illustrations	Figure 1-1	Installing and Removing the 11A81 Amplifier	1-4
	Figure 2-1	Measurement of Plug-in Contribution to Aberrations	2-11
	Figure 3-1	FRU and FRU IC Locator	3-16
	Figure 3-2	Removing/Replacing the Front Panel	3-18
	Figure 3-3	Components of the Front Panel Assembly	3-19
	Figure 3-4	Removing/Replacing the BNC Connector Assembly and the	
	•	A2 Front Panel Board	3-20
	Figure 3-5	Removing/Replacing the Cal Relay	3-22
	Figure 3-6	Removing/Replacing the A1 Main Board	3-26
	Figure 3-7	Torx Screw and Nut Block Orientation	3-27
	Figure 3-8	Removing/Replacing the Presampler Heat Sink	3-28
	Figure 3-9	Removing/Replacing a Hypcon Assembly	3-30
	Figure 3-10	Semiconductor Indexing Diagram	3-34
	Figure 3-11	IC Insertion-Extraction Pliers	3-35
	Figure 3-12	Multi-Pin Connector Orientation	3-38
	Figure 4-1	11A81 Amplifier System Functional Block Diagram	4-1
	Figure 4-2	11A81 Amplifier Detailed Block Diagram	4-4
	Figure 5-1	Exploded View of the 11A81 Amplifier	5-6
List of Tables	Table 2-1	Measurement Limits, Specifications, and Adjustments	2-1
	Table 2-2	Test Equipment	2-3
	Table 2-3	11A81 DC Accuracy Error Limits	2-19
	Table 2-4	11A81 Amplifier DC Offset Accuracy	2-22
	Table 2-5	11A81 DC Balance Error Limits	2-24
	Table 3-1	Board FRUs	3-8
	Table 3-2	Component/Module FRUs	3-8
	Table 3-3	Amplifier Kernel Error Index Codes	3-9
	Table 3-4	Self Tests/Extended Diagnostics Error Index Codes	3-9
	Table 3-5	Enhanced Accuracy Error Index Codes	3-10
	Table 3-6	Sample and Hold Board Failure Codes	3-11
	Table 3-7	Relative Susceptibility to Damage from Static Discharge	3-13
	Table 3-8	FRU Removal/Replacement Procedures	3-14

General Information

This reference is designed for use by qualified service personnel. It contains service information necessary to check, maintain and troubleshoot the 11A81 Amplifier.

Troubleshooting is primarily based upon internal diagnostics. These diagnostics isolate problems to the field replaceable unit (FRU) level. Once the faulty FRU is identified, use the procedures in this manual to remove and replace the faulty FRU. Section 5, *Replaceable Parts* gives a complete list of the FRUs in this amplifier

The 11A81 is a single channel, wide-bandwidth plug-in amplifier designed for use in CSA 404 and 11403A mainframes only. Commands from the oscilloscope control all the functions of the amplifier. The front panel of the amplifier has a button and an LED indicator for the input channel. Other controls and status indicators are located on the oscilloscope.

The impedance for both the display channel and the EXTERNAL TRIGGER input is $50~\Omega$. The display channel provides a display and a trigger output to the oscilloscope.

Each input has a TEKPROBE® input connector. The TEKPROBE® input connector is compatible with a Level 1 or Level 2 TEKPROBE®, a probe with a BNC connector, or a BNC connector. When a probe is connected to the display input connector, the amplifier will detect the probe-encoding information, and use this information to automatically achieve the appropriate settings. The EXTERNAL TRIGGER input does not sense the probe encoding and, so, does not adjust for any probe attenuation.

This reference contains the following sections:

- General Information discusses information that you should know about the 11A81 before you service it, such as safety information, installation and removal, available options and packaging suggestions.
- Checks and Adjustments describes the procedures for examining and adjusting the measurement limits and electrical specifications of the 11A81.
- Maintenance contains information for performing preventive maintenance, diagnosing faulty field replaceable units (FRUs), and corrective maintenance on the 11A81. This section includes replacement procedures for all FRUs.
- Theory of Operation discusses the general operation and signal path of the 11A81.
- Replaceable Parts provides you with a complete list of replaceable parts found on the 11A81 and an exploded view illustration showing all mechanical parts and FRUs.

Safety Summary

This general safety information is directed to operators and service personnel. Specific warnings and cautions will be found throughout the manual where they apply, but may not appear in this summary.

Terms in Manuals

caution statements in manuals identify conditions or practices that could result in damage to the equipment or other property.

warning statements in manuals identify conditions or practices that could result in personal injury or loss of life.

Terms on Equipment

CAUTION on equipment warns you of a possible personal injury hazard not immediately accessible as you read the marking, or a hazard to property; including the equipment itself.

DANGER on equipment indicates that you are exposed to a personal injury hazard as you read the marking.

Symbols in Manuals



Static Sensitive Devices

Symbols on Equipment







Protective ground (earth) terminal



ATTENTION Refer to manual

Power Source

This amplifier is intended to operate in a oscilloscope connected to a power source that will not apply more than 250 V rms between the supply conductors or between either supply conductor and ground. A protective ground connection, by way of the grounding conductor in the oscilloscope power cord, is essential for safe system operation.

Grounding the Product

This amplifier is grounded through the grounding conductor of the oscilloscope power cord. To avoid electric shock, plug the oscilloscope power cord into a properly wired receptacle before installing the amplifier. A protective-ground connection, through the grounding conductor in the oscilloscope power cord, is essential for safe operation.

1-2 General Information

Danger Arising from Loss of Ground

Upon loss of the protective-ground connection, all accessible conductive parts (including knobs and controls that may appear to be insulating), can render an electric shock.

Do Not Operate in Explosive Atmospheres

To avoid explosion, do not operate this product in an atmosphere of explosive gasses.

Do Not Service Alone

Do not perform internal service or adjustment of this product unless another person capable of rendering first aid and resuscitation is present.

Use Care When Servicing with Power On

Dangerous voltages exist at several points in this product. To avoid personal injury, do not touch exposed connections and components while the power is on.

Disconnect the power before removing protective panels, or replacing components.

Installing and Removing an Amplifier

Install the 11A81 in an 11403A or CSA 404 oscilloscope as follows:

1. Set the oscilloscope ON/STANDBY switch to STANDBY. Power must be off to prevent damage to both the amplifier and the oscilloscope.



If the green indicator light remains on when the STANDBY position is selected, then the switch was internally disabled when the power supply was serviced. To enable the ON/STANDBY switch, refer to the Maintenance section of the Service Reference manual for your oscilloscope.

- 2. Align the grooves in the top and bottom of the amplifier with the guides in the oscilloscope plug-in compartment. See Figure 1-1.
- 3. Insert the amplifier into the compartment until the front panel of the amplifier is flush with the front panel of the oscilloscope.

Remove the amplifier from the mainframe as follows:

- 1. Set the oscilloscope ON/STANDBY switch to STANDBY.
- 2. Pull the release latch (see Figure 1-1) to disengage the amplifier from the oscilloscope.
- 3. Slide the amplifier straight out of the plug-in compartment.

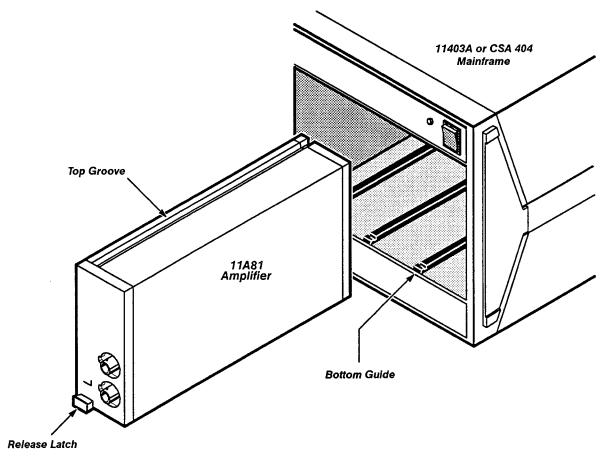


Figure 1-1 — Installing and Removing the 11A81 Amplifier

1-4 General Information

Instrument Options

Your amplifier might be equipped with one or more options. For further information and prices, see your *Tektronix Products Catalog* or contact your local Tektronix service center.

Packaging for Shipment

Save and reuse the original carton and packaging, if possible, when shipping the amplifier by commercial transportation. Package and ship amplifier and oscilloscopes separately.

Attach a tag to the amplifier if you ship it to a Tektronix service center for service or repair. Include the following information on the tag:

- Name and address of the amplifier owner
- Name of a person at your firm who can be contacted about the amplifier
- Complete amplifier type and serial number
- A description of the service required

Package the amplifier as follows, if the original package is not available or is not reuseable:

- Obtain a corrugated cardboard carton with inside dimensions at least six inches (15 cm) greater than the amplifier dimensions. Use a carton with a bursting test strength of at least 200 pounds per square-inch.
- 2. Fully wrap the amplifier with anti-static sheeting, or its equivalent, to protect the finish.
- Tightly pack dunnage or urethane foam between the carton and the amplifier to cushion the amplifier on all sides. (Allow three inches of packing on each side.)
- 4. Seal the carton with shipping tape or with industrial staples.
- 5. Mark the address of the Tektronix service center and your return address on the carton in one or more prominent places.

Operating Environment

The following environmental requirements are provided so that you can ensure proper functioning and extend the operation of the amplifier:

- Operate the amplifier in an oscilloscope where the ambient air temperature is between 0° and +50°C.
- Store the amplifier in ambient temperatures from -40° to +75°C.
- After storing the amplifier at temperatures outside the operating limits, allow the amplifier to reach the safe operating temperature before installing it in the oscilloscope, and applying power to the oscilloscope.

Enhanced system accuracy is available after a 20-minute warmup period. If the oscilloscope is in the Enhanced Accuracy state and the internal temperature of the oscilloscope changes $\pm 5^{\circ}$ C, the oscilloscope reverts to normal accuracy.

1-6 General Information

Checks And Adjustments

This section contains procedures to check the 11A81 specifications and measurement limits as listed in Table 2-1. To use these procedures as a test of instrument functionality or as an incoming inspection, perform only the procedures with "yes" in the Functional Test column. Perform the full sequence of procedures following repair or as part of a routine maintenance program. The Specification or Measurement Limit checked by a procedure is listed at the beginning of the procedure.

To ensure accurate operation, check the electrical adjustment after each 2,000 hours of operation; or every 24 months if you use the 11A81 infrequently.

Refer to the 11A81 User Reference for more information about advertised specifications and operation. Table 2-2, Test Equipment, lists the test equipment used in the procedures. Each procedure begins with an illustration that shows the equipment required for that procedure.

Table 2-1 — Measurement Limits, Specifications, and Adjustments

Part and Description	Measurement Limits (Examine)	Specifications (Check)	Adjustments (Adjust)	Functional Test
Procedure 1 Power-On	none	none	none	yes
Procedure 2 Enhanced Accuracy	none	none	none	yes
Procedure 3 Step Response/ Bandwidth	Aberrations during first 20 ns: +12%, -10%, total of 12% p-p at 50 mV/div	Risetime ≤ 130 ps; bandwidth=0.38/T _r	HOLD-C for specified aberra- tions and risetime	no
Procedure 4 Input Bias Current and Input Impedance	Input bias current ≤10 µA (at zero offset)	none	none	yes
	Input impedance of 50 Ω \pm 0.5 Ω			
Procedure 5 Oscilloscope Characterization	none	none	none	yes
Procedure 6 △V DC Accuracy		Using a CSA 404 or 11403A Oscillo- scope; ±0.60% +0.01 div	none .	yes

Table 2-1 — Measurement Limits, Specifications, and Adjustments (cont)

Part and Description	Measurement Limits (Examine)	Specifications (Check)	Adjustments (Adjust)	Functional Test
Procedure 7 DC Offset Accuracy		Offset within ± (0.53% + 0.01 div) of the vertical offset setting (refer to Table 2-4 for specific offset error and vertical offset settings)	none	yes
Procedure 8 DC Balance		Balance within ± 0.1 division	none	yes
Procedure 9 Internal Trigger		Sensitivity ≥2.0 div at 625 MHz.	none	yes
Procedure 10 External Trigger		40 mV p-p at 200 MHz; 150 mV p-p at 800 MHz; 200 mV p-p at 2 GHz	none	yes

Test Equipment

Table 2-2, Test Equipment, lists equipment recommended for use with the procedures in this manual. The Functional Test column of Table 2-2 indicates, with a check mark (ν), the test equipment that is recommended if you are performing only a functional test of the 11A81. Procedure steps are based on the test equipment examples given, but other equipment with similar specifications can be substituted. Test results, setup information, and related connectors and adapters might be altered if you use different equipment.

Table 2-2 — Test Equipment

Description	Minimum Specification	Examples of Recommended Test Equipment	Functional Test
11000-Series Oscilloscope compatible with the 11A81	TEKTRONIX CSA 404 or 11403A	TEKTRONIX CSA 404 or 11403A	V
Calibration Generator	Period, 0.1 ms - 10 μs, variable amplitude to 100 V p-p, rise time, <1 ns aberrations after 1 μs <0.1%	TEKTRONIX PG 506A Calibration Generator with a TM 500-Series Power Module	~
DC Voltage Calibrator	Output, 0-4 V, accuracy ≤0.01%	Data Precision 8200 Fluke 5440B, Fluke 343A	ν
Pulse Generator	Output, T _r <30 ps	Tektronix Part 067-1338-00	
Sinewave Generator	Frequency 200 MHz to 2 GHz	Wiltron 6709B	ν
Digital Multimeter (w/test leads)	Accuracy ≤0.01%	Fluke 8842A Digital Multimeter	V
Terminal	Terminal with an RS-232-C serial port	Compaq II with communications software	
Serial Cable for use with Terminal	RS-232-C Cable	Tektronix Part 012-0911-00	
Coaxial Cable, 18" (3 required)	50 Ω , 18-inch, male BNC connectors	Tektronix Part 012-0076-00	V
Coaxial Cable, 36"	50 Ω , 36-inch, male BNC connectors	Tektronix Part 012-0482-00	V
Power Divider, 50 Ω	Impedance 50 Ω SMA connectors	Tektronix Part 015-0565-00, (SMA female connectors)	V
Adapters	BNC female-to-dual banana (2 required)	Tektronix Part 103-0090-00	V
	SMA male-to-BNC female (3 required)	Tektronix Part 015-1018-00	V
	SMA female-to-BNC male	Tektronix Part 015-0572-00	

Table 2-2 - Test Equipment (Cont.)

Description	Minimum Specification	Examples of Recommended Test Equipment	Functional Test
Connector, T	BNC, T: two female and one male BNC connector	Tektronix Part 103-0030-00	V
Attenuator, 5X (2 required)	14 dB attenuation, 50 Ω , one male and one female BNC connector	Tektronix Part 011-0060-02	V
FRU Replacement Tools	Magnetic Screwdriver/ Holder for tips		
	Torx® Screwdriver Tips #6 tip #8 tip #10 tip (long shank) #15 tip		
	Pozidrive® Screwdriver Tips #1 tip		
	IC insertion-extraction pliers, 28-pin type	General Tool P/N U505BG or equivalent	
	Thermal Grease	(see Replaceable Parts in this manual)	
	24-pin Socket	Tektronix Part 136-0751-00	
	Open Ended Wrench, 5/16"		
	Needle-nose pliers		
	Tweezers		
	Static Control Mat		
	Wrist Strap		

Using These Procedures

The first-time user should familiarize themselves with the preceding information prior to performing the procedures that follow.

Conventions in this Manual

In these procedures, the following conventions are used:

- CAPITAL letters within the body of text identify front panel controls, indicators, and connectors on the oscilloscope/amplifier (for example, MEASURE).
- **Bold** letters identify menu labels, display messages, and commands typed in from a terminal or controller.
- Initial Capital letters identify connectors, controls, and indicators on associated test equipment (for example, Position).
- In some steps, the first word is italicized to identify a step that contains a performance verification and/or an adjustment instruction. For example, if Check is the first word in the title of a step, an electrical specification is checked. If Adjust appears in the title, the step involves an electrical adjustment. If Examine is the first word in the title, the step involves measurement limits that are used as calibration guides; these limits are not to be interpreted as electrical specifications.

Initialized Settings

At the beginning of most steps, you are instructed to **Initialize** the oscilloscope as part of the setup. The **Initialize** feature, available through the UTILITY menu, presets all oscilloscope controls and functions to known values. Initializing the oscilloscope at the beginning of a step eliminates the possibility of settings from previous procedures causing erroneous or confusing results.

Menu Selections and Measurement Techniques

Details on measurement techniques and instructions for making menu selections are generally not included in this manual. Comprehensive descriptions of menus and oscilloscope features are located in your oscilloscope *User Reference*.

Procedure 1 Power-On

This procedure prepares the oscilloscope, the 11A81, and the test equipment for the procedures that follow. This procedure also provides a warm-up period for all equipment. Perform all of the procedures in this section within the ambient temperature range of $+18^{\circ}$ and $+28^{\circ}$ C, to ensure that the oscilloscope and amplifier operate properly.

Setup to Power-On

CSA 404 or 11403A •=• 11A81 EXT : TRIG CH 1 : (not installed yet)

EAUTION }

Avoid damage to equipment by setting the mainframe ON/STANDBY switch to STANDBY before installing or removing plug-in units.

Procedure to Power-On

Step 1:	Perform the following settings in the order listed:
CSA 404	mplifier not installed yet 4 or 11403A STANDBY switch STANDBY
Step 2:	Install the 11A81 Amplifier in the CENTER compartment.
•	Ensure that the oscilloscope rear panel PRINCIPAL POWER SWITCH OFF and then connect the oscilloscope to a suitable power source.
•	Set the oscilloscope rear panel PRINCIPAL POWER SWITCH to ON the front panel ON/STANDBY switch to ON.
•	Power on the following test equipment so that it warms up with the r to be tested:
Cali Puls High Pow	tal multimeter bration generator ee Generator n frequency sine wave generator eer supply
i 🗀 FTT	III (a)

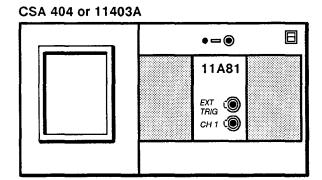
Table 2-2 gives a complete list of recommended test equipment.

Procedure 2 Enhanced Accuracy

This procedure ensures that the 11A81 and oscilloscope can achieve the Enhanced Accuracy state. When displayed, the Enhanced Accuracy symbol (EA) indicates that the amplifier and oscilloscope are at their highest accuracy state. The amplifier saves the calibration time and the ambient temperature, since this data is used in maintaining the Enhanced Accuracy state.

For more information about the Enhanced Accuracy state, refer to the oscilloscope *User Reference* manual.

Setup to Achieve Enhanced Accuracy



Procedure to Achieve Enhanced Accuracy

Step 1: Initialize the oscilloscope settings, then perform the following settings in the order listed:
11A81 Amplifier no settings required CSA 404 or 11403A no setting changes
Step 2: Twenty minutes after power-on, the oscilloscope must recalibrate itself to achieve the Enhanced Accuracy state. Press the ENHANCED ACCURACY button. A prompt then appears on the display. Press the ENHANCED ACCURACY button again. The system should achieve Enhanced Accuracy after a couple of minutes.

CAUTION

Turning the oscilloscope power off during Enhanced Accuracy testing may result in losing some of the non-volatile RAM data. This could cause diagnostic errors at the next power-up, and cause the oscilloscope to operate unpredictably. If this event occurs, refer to Restoring Calibration Data in your oscilloscope Service Reference manual.

Step 3: Ensure that the message, **Enhanced Accuracy in Progress** appears, indicating that the oscilloscope is attempting to achieve Enhanced Accuracy.

Step 4:	Examine that the message, Enhanced accuracy completed and
passed	ndicating that the Enhanced Accuracy state has been achieved
appears	The EA indicator appears on the display below the vertical scale
indicato	while in the Enhanced Accuracy state.

Procedure 3 Step Response/ Bandwidth

This procedure examines and adjusts, if necessary, the display step response and calculates the bandwidth. To facilitate adjustments during this procedure, you will need to connect a terminal and configure the mainframe to allow changing of calibration settings. The risetime specification does not include contributions from the generator or from averaging the time jitter.

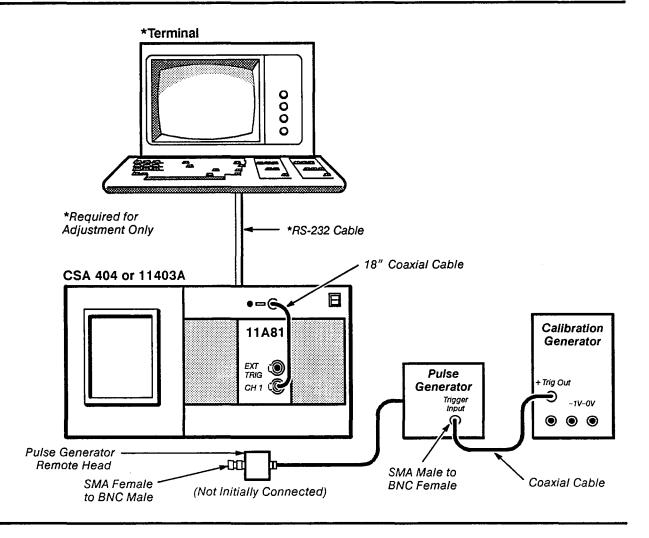
Specifications

Risetime \leq 130 ps; Bandwidth is calculated from the measured risetime using the formula: BW = $0.38/T_r$ (risetime).

Measurement Limits

High-frequency aberrations during the first 20 ns, + 12%, -10%, or 12% p-p maximum at 50 mV/div.

Setup to Check/Adjust Step Response and Bandwidth



,,,	, ccu	are to officer/Adjust step fresponse and odiodiate buildwidth				
	•	o 1: Initialize the settings and then perform the following settings in the er listed:				
	Calibration Generator 1 μs Mode Fast Rise					
	Puls	se Generator				
		Power ON ninal on 81 Amplifier				
		CH 1 display on/off				
	Step	2: Calibrate CH1 signal path as follows:				
	=	Press the UTILITY button then select Probes from the Utility major menu.				
	•	Touch C1 to initiate probe calibration on CH 1.				
	•	When the message Probe cal complete. Deskew passed appears, select Exit Comp . This completes the probe calibration of CH 1.				
		3: Disconnect the coaxial cable from CH 1 and connect the Pulse lerator Remote head to CH 1.				
		4: To setup the risetime measurement, perform the following settings in order listed:				
		Vert Size				
		Acquire Desc Acquire Desc pop-up menu Average N (defaults to 32 averages) Measure major menu				
		5: Observe the Stats Comp Test & Def status and wait until the nple number reaches 100.				
		Vert Size				

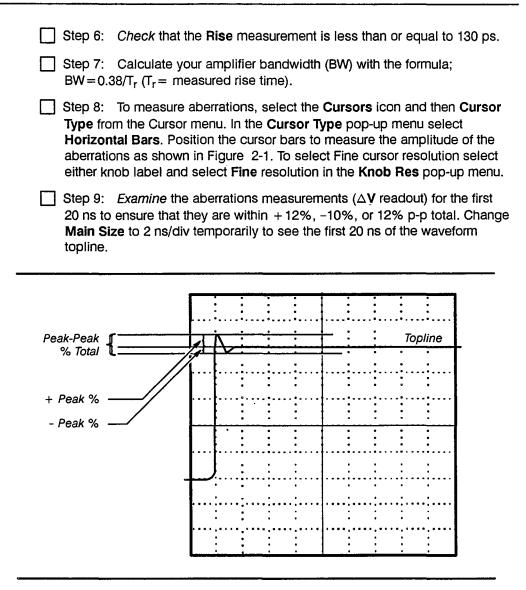


Figure 2-1 — Measurement of Plug-in Contribution to Aberrations



DO NOT attempt to adjust the display step response adjustment HOLD-C if the waveform is within the stated limits. Proceed to Procedure 4.

The step response adjustment requires the entry of a calibration constant via the terminal shown in the Procedure 3 setup illustration.

- Step 10: Locate the CSA 404 or 11403A calibration jumper pins, J450, on the A6 Time Base board and install a black, short-circuit jumper across the pins.
- Step 11: Locate the J1630 jumper pins on the 11A81 Amplifier, and install the black, short-circuit jumper in the UID position, across Pins 1–2. See Figure 3-1 on page 3-16 for the jumper location.

	Step 12: 9600.	Determine the baud rate of your terminal; the mainframe default is
	•	Set the oscilloscope Baud Rate to match the baud rate of the out
	■ Press	the UTILITY button twice, and then touch RS232C.
	■ Set th	ne Baud Rate to match the baud rate of the terminal you are using.
	■ Set E	cho and Verbose to On.
(mo cou -1.	ost overshould compro 1 should b	in constant (84) should be set to a $<$ value $>$ within the range -1.1 bot) to $+0.65$ (least overshoot). Exceeding the recommended range omise other parameters unrelated to overshoot. (The initial value of e used after replacement of the NVRAM or the Presampler IC and as needed.)
	•	Check the current setting of the 11A81 installed in the CENTER nent by entering the command:
	CCA? 84	1
	•	r is installed in the LEFT or RIGHT compartment use the command?, respectively.
		Adjust the display step response adjustment HOLD-C (84) to epecified performance. On the terminal keyboard, enter the
	CCA 84:	<value></value>
		ct on the displayed waveform and try a new value as necessary. The non-linear across the possible range.
		If you changed the HOLD-C value, then the low frequency gain has red. Repeat Procedures 2 and 3 to restore Enhanced Accuracy and that the step response is still within specifications.
	Step 17: (J1630) a	Replace the calibration jumpers to original positions on the 11A81 nd the CSA 404 or 11403A (J450).

Procedure 4 Input Bias Current and Input Impedance

This procedure examines the input bias current at zero offset, and it examines the input impedance.

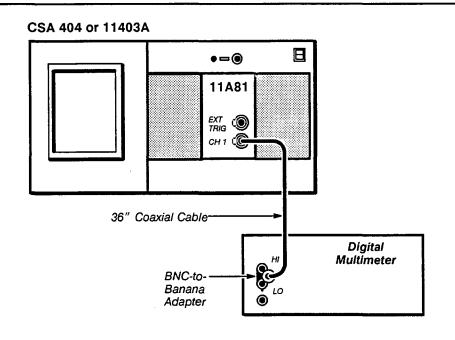
The system must be in the Enhanced Accuracy state for this procedure.

Measurement Limits

The measurement limits are as follows:

- Open circuit bias current 10 µA at zero offset
- Input impedance = $50 \pm 0.5 \Omega$

Setup to Examine Input Voltage and Input Impedance



Procedure to Examine Input Bias Current and Input Impedance

	-	Initialize the oscilloscope settings, then perform the following in the order listed:
	11A81 A	mplifier
	СН	1 display on/off
	CSA 404	or 11403A
	Vert	Size
	Digital n	nultimeter (DMM)
	Ran	ge 200 mA DC
	Step 2:	Examine the DMM for a reading of 0 $\mu A,$ within the limits of $\pm10~\mu A.$
\Box	Sten 3:	Set the DMM to the 200 O range

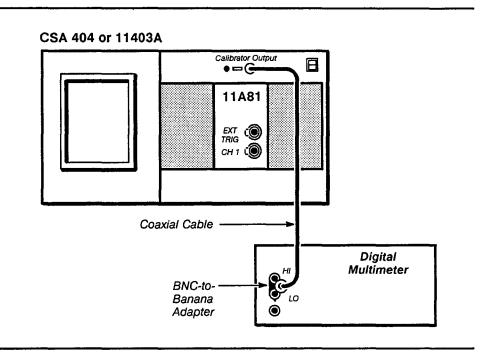
Procedure 4 Input Bias Current and Input Impedance

Step 4:	Read the DMM and record the value as Z_1 for later use.
Step 5: DMM.	Reverse the connection of the BNC-to-dual banana adapter on the
•	Read the DMM, and then record this value as Z_2 . Calculate the nce average by adding Z_1 and Z_2 and dividing the result by 2.
	Examine that the average impedance value is within the limits of

Procedure 5 Oscilloscope Characterization

This procedure determines a characterization factor for the oscilloscope calibration voltage reference. You will use the characterization factor determined in this procedure in performing Procedures 6 and 7.

Setup to Characterize the Oscilloscope



Procedure to Characterize the Oscilloscope

	•	Initialize the oscilloscope settings, then perform the following in the order listed:	
	11A81 Amplifier no setting changes CSA 404 or 11403A		
	UTI	LITY menu Extended Diagnostics	
	0	Subsys Digitizer	
		Block Points Acq	
		Area FP Cal Refs	
		Routine FP -10.000 V	
		Run touch	
	Step 2:	Record the absolute value reading of the DMM as V_1 for later use.	
	Step 3:	Touch Exit to end the FP -10.000 V diagnostic test.	
	Step 4:	Select the FP + 9.9951 V Routine.	
	Step 5:	Touch Run.	
	Step 6:	Record the DMM reading as V ₂ for later use.	
П	Step 7:	Touch Exit to end the FP +9.9951 V diagnostic test.	

Procedure 5 Oscilloscope Characterization

Step 8: mode.	Touch Exit Diagnostics twice to exit the Extended Diagnostics
	Add the absolute values of $\rm V_1$ and $\rm V_2$. Divide the result by 19.9951 \n the characterization factor of the oscilloscope calibration voltage e.
	ne characterization factor just obtained is required to perform

Procedure 6 △V DC Accuracy

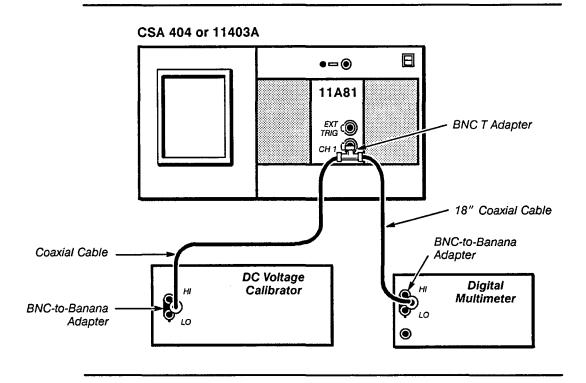
This procedure checks system ΔV DC accuracy using a precision digital multimeter and a precision power supply. The system must be in the Enhanced Accuracy state during this procedure.

This procedure confirms that the amplifier can be accurately calibrated. This procedure does not test for oscilloscope accuracy or long term stability. Therefore, the characterization factor of the oscilloscope's calibration voltage reference must be calculated in Part 5, Oscilloscope Characterization. Also, you should perform this procedure immediately after entry into the Enhanced Accuracy state.

Specifications

 Δ V DC Accuracy must be within \pm (0.6% +0.01 div) with an eight division voltage change.

Setup to Check $\triangle V$ DC Accuracy



Procedure to Check ΔV DC Accuracy

If the environment is electrically noisy, connect a capacitor (at least 0.1 μ F) across the input terminals of the digital multimeter.

- Step 1: Press the ENHANCED ACCURACY button twice to initiate Enhanced Accuracy calibration and ensure peak performance of the system.
- Step 2: **Initialize** the oscilloscope settings, then perform the following settings in the order listed:

step 2: Initialize the oscilloscope settings, then perform the following settings in the order listed:
11A81 Amplifier
CH 1 Display on/offon Mainframe
Acquire Desc touch
Average N On
DC Voltage Calibrator
On/Standby
50 Ω Override on Digital multimeter (DMM)
Mode DC
Range auto
Step 3: Set the oscilloscope to measure the ΔV DC accuracy as follows:
■ Press the MEASURE button.
■ Touch Measurements and then Mean in the Measurements pop-up menu. Touch Exit Menu to finish the measurement selection.
■ Touch Mean in the MEASURE major menu, and then touch Data Interval to select Whole Zone in the Mean pop-up menu.
■ Touch Stats Comp Test & Def and then touch Compare Options.
■ Touch Compare to toggle it to On . The △ Mean measurement readout now shows a difference or delta measurement.
Step 4: Set Vert Size to the first Vertical Size entry in Table 2-3.
Step 5: Set the DC Voltage Calibrator polarity to minus (-), then set its output level to the appropriate Deflection Volts setting from Table 2-3. Check the DMM to ensure the correct voltage setting. (If you apply too high a voltage level, the input coupling will be switched to Off. If this happens, use Couping in the Waveform major menu to set coupling back to DC.)
Step 6: Save the current Mean measurement (0 V) as the reference value:
■ Touch Stats Comp Test & Def and then touch Compare Options.
■ Touch Measure Selected Wfm Save as References to save the current Mean measurement as a reference.
Step 7: Set the DC Voltage Calibrator polarity to plus (+), leaving its output level set to the current Table 2-3 Deflection Volts. Check the DMM to ensure the correct voltage setting.
Step 8: Clear the waveform data by selecting Remove/Clr Waveform , then selecting Clear waveform name (wfm 1) in the pop-up menu. This restarts waveform averaging and gives a measurement based on the new signal level.

- Step 9: Now calculate the $\triangle V$ DC error:
 - Read the current △Mean measurement.
 - Divide the △Mean value by the mainframe characterization factor that you determined in Procedure 5.
 - Subtract from this value, 2 times the present Deflection Volts setting to obtain the ΔV DC error. For example: $(8.012/.996) (2 \times 4 \text{ V}) = 0.044$.
- Step 10: Check that the ΔV DC error obtained in Step 9 is within the Error Limits for the current Vertical Size given in Table 2-3. (For the above example, the calculated ΔV DC (44 mV) is less than the allowed Error Limit 58 mV.)
- Step 11: Repeat Steps 4 through 10 for the remaining Vertical Size settings listed in Table2-3.

Table 2-3 - 11A81 DC Accuracy Error Limits

Vertical Size	Deflection Volts	Error Limits (±V)
1 V/div	4 V	58.0 mV
500 mV/div	2 V	29.0 mV
200 mV/div	800 mV	11.6 mV
100 mV/div	400 mV	5.8 mV
50 mV/div	200 mV	2.9 mV
20 mV/div	80 mV	1.16 mV
10 mV/div	40 mV	0.58 mV

Procedure 7 DC Offset Accuracy

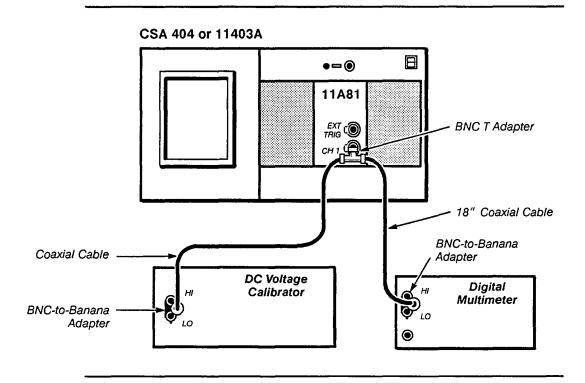
The system DC Offset is checked using a precision digital multimeter and a power supply.

This procedure confirms that the amplifier can be accurately calibrated. This procedure does not test for oscilloscope accuracy or long term stability. Therefore, the characterization factor of the mainframe calibration voltage reference must be calculated in Procedure 5, Oscilloscope Characterization. Also, you must perform the DC Offset Accuracy procedure immediately after entry into the Enhanced Accuracy state.

Specifications

The offset error must be within \pm (0.53% +0.01 div) of the vertical offset setting. Refer to Table 2-4, 11A81 Amplifier DC Offset Accuracy, for specific values for each vertical offset setting.

Setup to Check DC Offset Accuracy



Procedure to Check DC Offset Accuracy

If the environment is electrically noisy, then connect a capacitor (at least 0.1 μ F) across the input terminals of the digital multimeter (DMM).

Step 1: Press the ENHANCED ACCURACY button twice twice to initiate Enhanced Accuracy calibration and ensure peak performance of the system.

	Step 2: Initialize the oscilloscope settings, then perform the following settings in the order listed:
	DC Voltage Calibrator On/Standby on 50 Ω Override on Output Level 0 V 11A81 Amplifier On CH 1 display on/off on Mainframe Acquire Desc touch Average N On Digital multimeter (DMM) Mode Mode DC Range auto
	Step 3: Measure the position of the displayed waveform (it should be at 0 V on the graticule) as follows:
	■ Press the MEASURE button.
	■ Touch Measurements and then Mean in the Measurements pop-up menu. Touch Exit Menu to finish the measurement selection.
	■ Touch Mean in the MEASURE major menu, and then touch Data Interval to select Whole Zone in the Mean pop-up menu.
	■ Touch Stats Comp Test & Def and then touch Compare Options.
	■ Touch Compare to toggle it to On. The △Mean measurement readout now shows a difference or delta measurement.
	■ Touch Measure Selected Wfm Save as References to save the current Mean measurement (0 V) as the reference value.
	Step 4: Set Vert Size to the first entry (1 V/div) in Table 2-4.
	Step 5: Set Vert Offset to the corresponding Vertical Offset in Table 2-4.
	Step 6: Set the DC Voltage Calibrator Output Level to the current Vertical Offset divided by the characterization factor that you determined in Procedure 5. Check the DMM to ensure the correct voltage setting.
	Step 7: Clear the waveform data by selecting Remove/Cir Waveform , then selecting Clear waveform name (wfm 1) in the pop-up menu. This restarts waveform averaging and gives a measurement based on the new signal level.
	Step 8: Read the \triangle Mean measurement after it has stabilized. Subtract the Vertical Offset set in Step 5 from the \triangle Mean measurement to get the DC Offset Error.
	Step 9: Check that the DC Offset Error obtained in Step 8 is less than the Error Limit listed in Table 2-4 for the current Vertical Size.

Step 10: Repeat Steps 4 through 9 for each Vertical Size and Offset listed in Table 2-4.

Table 2-4 — 11A81 Amplifier DC Offset Accuracy

Vertical Size	Vertical Offset	Error Limit (±Volts)
1 V/div	4 V	31.3 mV
500 mV/div	4 V	26.2 mV
200 mV/div	2 V -	12.6 mV
100 mV/div	1 V	6.3 mV
50 mV/div	500 mV	3.15 mV
20 mV/div	200 mV	1.26 mV
10 mV/div	100 mV	0.63 mV
10 mV/div	50 mV	0.37 mV

±0,53% + 0.01 die

Procedure 8 DC Balance

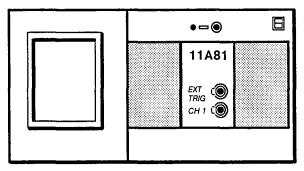
This procedure examines the position of the displayed trace with no input signal applied. It confirms that DC balance has been calibrated accurately. Drift over time or temperature is not tested. Therefore, you must perform this procedure immediately after entry into the Enhanced Accuracy state.

Specification

Balance within ± 0.1 division.

Setup to Check DC Balance

CSA 404 or 11403A



Procedure to Check DC Balance

Step 1: Initialize the oscilloscope settings, then perform the following settings in the order listed:
11A81 Amplifier CH 1 display on/off
Step 2: Measure the trace position as follows: Touch Acquire Desc in the Waveform major menu.

- Set Average N to On in the Acquire Description pop-up menu.
- Press the MEASURE button, and then touch Measurements.
- Touch Mean in the Measurements pop-up menu and then Mean in the MEASURE major menu.
- Touch Data Interval to select Whole Zone in the Mean pop-up menu.
- Step 3: Check that the **Mean** readout is within the Error Limit listed adjacent to the current Vert Size setting (1 V/div) in Table 2-5.
- Step 4: Repeat Step 3 for each Vert Size setting in Table 2-5. Allow 10 seconds for the **Mean** measurement to settle after each Vert Size change.

Table 2-5 — 11A81 DC Balance Error Limits

Vert Size	Error Limit	
Setting	(0.1 div)	
1 V/div	100 mV	
500 mV/div	50 mV	
200 mV/div	20 mV	
100 mV/div	10 mV	
50 mV/div	5 mV	
20 mV/div	2 mV	
10 mV/div	1 mV	

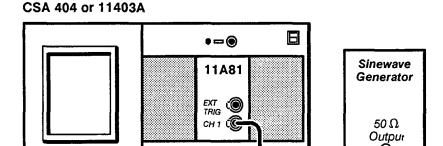
Procedure 9 Internal Trigger

This procedure examines the sensitivity of the internal trigger to an applied input signal. The internal trigger signal is derived from the CH 1 input. The internal trigger is checked at the minimum specified amplitude for the rated bandwidth.

Specification

Sensitivity of 2.0 divisions or less at 625 MHz.

Setup to Check the Internal Trigger



Coaxial Cable

Procedure to Check Internal Trigger

Step 1: Initialize the oscilloscope settings, then perform the following settings in the order listed:

11A81 Amplifier
CH 1 Display on/off
On Sinewave Generator
Frequency
Frequency
Amplitude
CSA 404 or 11403A
Vertical Size
Vertical Size
1 ns/div

Step 2: Touch the Trigger icon.

Step 3: Check that you can adjust the Trigger Level for a triggered display.

Procedure 10 External Trigger

This procedure checks the sensitivity of the EXTERNAL TRIGGER INPUT to an applied input signal. The procedure checks that the External Trigger circuit can trigger on signals at the minimum specified amplitude for each frequency in the following Specification.

Specification

Trigger sensitivity is at least:

- 40 mV p-p at 200 MHz
- 150 mV p-p at 800 MHz
- 200 mV p-p at 2 GHz

Setup to Check the External Trigger

CSA 404 or 11403A •••• 11A81 5X Attenuators 50 Ω Generator 18" Coaxial Cables SMA Power Divider

Procedure to Check External Trigger

Step 1: Initialize the oscilloscope settings, then perform the following settings in the order listed:
11A81 Amplifier
CH 1 display on/off on
CSA 404 or 11403A
Vertical Size10 mV/div
Main Size 2 ns/div
Sinewave Generator
Frequency 200 MHz
Amplitude (4 divisions as measured on display) 40 mV p-p
Step 2: Press the TRIGGER major menu button and then select Source Desc.

with BNC to SMA Adapters

	Ш		Touch C2 External then Enter Desc to select the EXTERNAL R as the trigger source.
		Step 4:	Check that you can adjust the Trigger Level for a triggered display.
		Step 5:	Set the Vertical Size to 20 mV/div.
		Step 6:	Set the Main Size to 1 ns/div.
		Step 7:	Set the Sinewave generator Frequency to 800 MHz.
*] = \$ \$ [*] # * *		amplitud level of difference	Set the Sinewave generator Amplitude for a displayed signal le of 145 mV p-p (7.25 divisions). This setting will ensure a signal 150 mV p-p at the EXTERNAL TRIGGER INPUT. Small impedance ses cause this discrepancy between the displayed amplitude and the trigger amplitude.
		Step 9:	Check that you can adjust the Trigger Level for a triggered display.
		Step 10:	Set the Main Size to 500 ps/div.
		Step 11:	Set the Sinewave generator Frequency to 2 GHz.
		amplitud	Set the Sinewave generator Amplitude for a displayed signal lee of 160 mV p-p (8 divisions). This setting will ensure a signal level of p-p at the EXTERNAL TRIGGER INPUT.
		Step 13:	Check that you can adjust the Trigger Level for a triggered display.

Maintenance

This section contains information for performing preventive maintenance, diagnostic troubleshooting, and corrective maintenance on the 11A16 Amplifier. Preventative Maintenance describes cleaning techniques that can extend the life of the 11A81. Diagnostic Troubleshooting describes the internal software diagnostics and provides information that relates diagnostic errors with suspect FRUs (field-replaceable units). The FRUs include circuit boards and some socketed components. Corrective Maintenance describes procedures for removal and replacement of FRUs and checks required after replacement. Service beyond this level must be done at a Tektronix service center.

For more information on the equipment used in this section refer to Table 2-2.

Preventive Maintenance

Preventive maintenance can prevent the amplifier from failing and will ensure reliable operation. The environment in which the amplifier is operated will affect the frequency of maintenance. For example, operation in a dusty environment will require more frequent cleaning of the plug-in unit to maintain proper component temperatures.

Amplifier Shield Removal

The side shields, top and bottom frames, and front panel reduce radiation of electromagnetic interference (EMI) from the amplifier. Grooves in the frame hold the side shields in place.

Remove a side shield as follows:

Step 1: Gently pry the side shield up from the rear of the 11A81.

Step 2: Lift up on the shield.

Step 3: Remove the shield from the grooves in the frame and front panel.

Install a side shield as follows:

Step 1: Position the shield over the frame grooves.

Step 2: Slide the front lip of the side shield under the front panel.

Step 3: Press down on the shield until it snaps into place. (Pressure must be applied along the full length of the frames to secure the shield.)

Note that the 11A81 will not slide into the mainframe if the side shields are not

Cleaning

fully seated in the frames.

The amplifier should be cleaned as often as operating conditions require. Dirt on components insulates them preventing efficient heat dissipation. Dirt also provides an electrical conduction path, which can lead to amplifier failure.

The side shields of the amplifier, reduce the amount of dust reaching the interior of the amplifier. Therefore, keep the amplifier side shields in place for safety and cooling (except when you are performing internal adjustments or maintenance procedures).

CAUTION

Avoid the use of chemical cleaning agents which might damage the materials in this amplifier: Use only isopropyl alcohol. Before using any other type of cleaner, consult your local Tektronix service center or representative.

Exterior — dust can be removed with a soft cloth or small brush. The brush is particularly useful for dislodging dirt in and around the side-shield ventilation holes and front panel switches. Remove the side shields before cleaning them.

Interior — cleaning the interior of the amplifier is seldom required. If the interior of the amplifier accumulates dust or dirt, clean with dry, low-velocity air. Remove any remaining dirt with a soft brush or a cloth dampened with isopropyl alcohol. A cotton-tipped applicator is good for cleaning in narrow spaces and for cleaning more delicate components. Finally, remove any cleaning residue with dry, low-velocity air.

CAUTION

To prevent damage from electrical shorts, the boards and components must be dry before applying power.

Visual Inspection

The amplifier should be inspected occasionally for loosely-seated or heat-damaged components. The corrective procedure for most visible defects is replacement; however, particular care must be taken if heat-damaged parts are found. Since overheating usually indicates other problems with the amplifier, correcting the cause of overheating is important to prevent the replaced part from being damaged.

Periodic Electrical Adjustment

To ensure accurate measurements, check the electrical adjustment of the amplifier after each 2,000 hours of operation; or every 24 months if you use the amplifier infrequently. Refer to *Checks and Adjustments* in this manual for the procedures necessary to check these electrical adjustments.

Diagnostic Troubleshooting

The 11A81 and its supporting mainframe automatically perform a series of diagnostic tests when powered on. The diagnostic tests generate error index codes for any failures. You can cross-reference an error index code to the suspect FRU(s) using the FRU Guide tables, Tables 3-1 and 3-2.

Note: Any diagnostic errors should be suspect until the 11A81 has achieved Enhanced Accuracy in its current mainframe configuration. Exit Extended Diagnostics and invoke Enhanced Accuracy (press the ENHANCED ACCURACY button twice). Upon successful completion of Enhanced Accuracy, run Self Test in the Utility major menu and check that no diagnostic errors occur. Diagnostic errors would put the instrument into the Extended Diagnostic menu with an error evident beside the 11A81 plug-in unit subsystem entry.

Diagnostics Overview

When power is applied, the 11A81 microprocessor (MPU) executes a set of Kernel tests to verify local functionality. If these tests are successful, then the mainframe starts the Self Tests to verify the functionality of each of the subsystems and their ability to communicate. Any Self Tests failure causes the oscilloscope to enter Extended Diagnostics and to display the error index code(s) in the Extended Diagnostics menu. Refer to your mainframe Service Reference for more information on Extended Diagnostics menus and operation. Error codes for the 11A81 Diagnostic tests are described later in this section.

The Kernel tests and Self Tests/Extended Diagnostics produce and format error index codes differently, and so these error index codes will be discussed separately.

Kernel Tests

Each time the front panel ON/STANDBY switch is set to ON, the mainframe and amplifier perform Kernel diagnostics on their microprocessor subsystems and Self Tests diagnostics on all of their major circuits.



Turning the mainframe power off during execution of the diagnostic tests can result in the lose of some or all data (for example, stored settings and calibration constants) from the non-volatile RAM (NVRAM). This loss of data can cause the oscilloscope to operate unpredictably. If this occurs, refer to Restoring Calibration Data later in this section.

After the amplifier is powered-on, the microprocessor unit (MPU) begins a sequence of test routines to determine if its Kernel systems are operating properly. If any of these tests fail, then it is unlikely that the amplifier can communicate the failure to the mainframe. In most cases, the mainframe will continue to power up without recognizing the faulty 11A81 plug-in amplifier.

The Kernel diagnostics communicate a fault by flashing a fault code on the front panel CH 1 LED. The fault code is an index to the failing Kernel test. Table 3-3 lists the possible error codes. The CH 1 LED will light very briefly as power is applied to the oscilloscope, but this is of much shorter duration than the two second lighting produced by the Kernel diagnostics.

Read the fault code as follows:

- If the amplifier Kernel tests detect a fault, then the CH 1 LED is flashed. The LED is on for approximately two seconds per flash.
- Count the number of times the CH 1 LED is lit.

If one of the following errors occur, refer to Table 3-3 for a list of suspect FRU's. Refer to the appropriate replacement procedure in Table 3-8.

The three 11A81 Kernel tests are:

- Test 1: The ROM Checksum test computes a checksum of the content of the firmware ROM. This calculated checksum is then compared with a checksum stored in the ROM. If the checksums do not match, the test fails and the CH 1 LED is flashed once. After the front panel LED flashes to report the fault code, the amplifier attempts to enter normal operation. However, it is unlikely that the amplifier can function properly as a bad ROM Checksum indicates a problem reading the EPROM.
- Test 2: The Non-volatile RAM (NVRAM) test verifies that the NVRAM is functioning properly. Since the NVRAM contains calibration information which must remain undamaged, this test does not alter critical data. If the testing algorithm detects a failure, then the amplifier reports a fault code of 2 by flashing the CH 1 LED twice. The amplifier continues looping the NVRAM test until the oscilloscope is powered off (ON/STANDBY switch is set to STANDBY). The mainframe does not recognize the amplifier until the condition causing the NVRAM test to fail is corrected.

The NVRAM test could corrupt data stored in the NVRAM if you power down the oscilloscope during this test. If corruption occurs, then the Calconstant Checksum will be corrupted as well. At the next power-on, the amplifier will reset the cal constants to default ROM settings and report a Plug-in (Amplifier) Calconstant Checksum Error during power-on diagnostics.

■ Test 3: The Serial Data Interface IC test — verifies the functionality of the Serial Data Interface (SDI) IC. The SDI IC performs the following housekeeping chores of the amplifier: channel sequencing, refreshing the analog control voltage system (ACVS), and providing serial data communications with the mainframe. This test exercises the SDI IC, and records the ICs signature using an algorithm similar to signature analysis. If the resulting signature of the SDI IC does not match a known good signature, then this test fails and the front panel CH 1 LED is flashed three times. If this test does fail, then the amplifier continues looping on this test as long as the oscilloscope is powered on, generating activity on all SDI IC pins.

After all power-on Kernel tests have completed successfully, the amplifier initializes its settings and communicates with the mainframe.

3-4 Corrective Maintenance

Self Tests

After the 11A81 successfully passes its Kernel tests, the oscilloscope requests that the amplifier execute its Self Test routines (unless the oscilloscope Self Tests are disabled). If the oscilloscope returns to normal operation or starts a new configuration calibration, this indicates successful completion of the Self Tests. Any failures cause the oscilloscope to display the Extended Diagnostics menu.

Self-Test diagnostics test the following:

- Probe coding
- Calibration (cal) constant checksums
- Calibration (cal) constant values
- Serial number storage
- Analog Control Voltage system (ACVS)
- Analog-to-digital converter
- Probe power protection circuits
- Signal path
- Mainframe compatibility
- RMS protection circuit
- Calibration voltage buffer circuit

Error Index Codes

The format of the error index codes is based on the Extended Diagnostics menu structure. Diagnostic error index codes are five digit codes whose first character indicates the subsystem or plug-in unit tested. The last four digits are hexadecimal (hex) numbers that indicate the Block, Area, Routine and failure identity. For example, R1311 is decoded as follows:

- R Subsystem Right Plug-in Amplifier
- Block name R_11A81
- 3 Area name Group III
- 1 Routine name ACVS Test
- 1 Failure identity specific failure mode

The subsystem character of an error index code is one of the following, and indicates the compartment in which the amplifier is installed:

L Left

C Center

R Right

The tables in this section, list only the four-digit failure code; the prefix L, C, or R is omitted.

Using the Self Tests/Extended Diagnostics

After all Self Tests/Extended Diagnostic are executed, any resultant error index codes appear on the display next to the associated circuit block names in the Extended Diagnostics menu. Each circuit block that experiences failure will indicate the first error encountered and the number of failures in the Block. To get a more complete list of the error index codes in a Block, touch the selector of a failed Block and then the Area selector. To display the lowest level test routines in the selected Area, touch the Routine selector.

Some diagnostic tests are not executed automatically during the Self Tests. These manual tests generate unique error index codes that can aid in troubleshooting failures. You can select and run the manual tests from the Extended Diagnostics menu.

Several operating mode selectors are available on the screen. When certain test routines are selected, some of these operating modes can not be selected.

Refer to your mainframe *User Reference* for more information on Extended Diagnostics menus and operation.

Enhanced Accuracy Errors

Enhanced Accuracy calibration can also generate error index codes whenever the calibration process fails. These error codes are listed in Table 3-6 with cross reference to the FRU(s) likely to have caused the failure. For an overview of the Enhanced Accuracy mode, refer to Procedure 2, Enhanced Accuracy in the Checks and Adjustments section of this manual. Refer to your mainframe User Reference for additional information.

Calibrating a New Configuration

When a amplifier is first installed in an oscilloscope or is moved to a different compartment in the oscilloscope, the oscilloscope enters a new configuration mode. After the oscilloscope executes the power-on diagnostics, it recalibrates itself for the new configuration. During this calibration, the message **Powerup new configuration partial calibration occurring** appears. If the calibration is successful then a message appears and the oscilloscope enters the normal operating mode.

Restoring Calibration Data

If the oscilloscope is powered off (ON/STANDBY switch set to STANDBY) during probe calibration, Self Tests, Extended Diagnostics or other intense system activity, then some internal data can be corrupted. If the Extended Diagnostic menu is displayed when the power is turned on, then this corruption might have occurred.

If the Extended Diagnostics menu displays a **Cksm Probe** error (this error indicates that the power was turned off during probe calibration), then use the following procedure to restore normal operation:

Step 1:	Note the amplifier at fault from the Extended Diagnostics menu.
Step 2:	Exit the Extended Diagnostics menu.

3-6 Corrective Maintenance

Scan by Zenith

	Remove and replace the probes on the amplifier at fault.
Step 4:	Recalibrate these probes.
	Execute the Self Tests in the Utility2 major menu, and confirm that ests pass.

If the Extended Diagnostics menu displays a **Serial Sum** or **Cksm Plug** error, the plug-in amplifier will require service. See *Programming the Unit Identification and Calibration Constants* on page 3-36 in this manual or contact your local Tektronix service representative.

Memory Backup Power for the Amplifier

The non-volatile RAM (NVRAM) within the amplifier allows the data in memory to be retained when the amplifier is removed.

The NVRAM stores system-configuration data such as the amplifier, oscilloscope, and probe identification numbers as well as the factory cal constants. The data that the NVRAM stores, enable the amplifier to resume Enhanced Accuracy performance from a powered-off condition, without performing a full calibration (Enhanced Accuracy) operation.

The rated lifetime of the NVRAMs internal power source is ten years. If, on system power-on, the amplifier habitually loses Enhanced Accuracy status without a system configuration change (that is, the amplifier remains plugged into the same slot in the same oscilloscope), then you may need to replace the NVRAM.

Field Replaceable Unit (FRU) Guide

This section correlates error index codes resulting from Diagnostic tests with the hybrid, integrated circuit (IC), module, or board FRU(s) suspected of causing each error. The FRU(s) in each category are listed in the order of most-to-least probable cause (assuming only one error is indicated). If any diagnostic errors occur, inspect the suspect FRU for loose connections and components and then repeat the Diagnostic test. If any diagnostic errors reoccur, then replace the suspect FRU(s) with a good FRU(s). Verify that the new FRU is a correct replacement for the old FRU. If the old FRU contains firmware, then verify that the new firmware version is either the same version as the old firmware or an updated version.

Abbreviations of FRU Names

Table 3-1, Board FRUs, lists the abbreviation used in the Suspect Board FRU(s) column of Tables 3-3, 3-6, 3-4 and 3-5.

Abbreviation Name Designator Main Main board **A**1 S/H1 Sample/Hold board (J1580) A1A1 Sample/Hold board (J1570) S/H2 A1A2 Front Front Panel board **A2 RMS Pickoff** А3 RMS Signal Pickoff board

Table 3-1 - Board FRUs

Abbreviations of Component and Module Names

Table 3-2, Component/Module FRUs, lists the abbreviation used in the Suspect Module, Hybrid, or IC FRU(s) column of Tables 3-3, 3-4 and 3-5.

Abbreviation	Name	Designator
EPROM	Firmware IC	U2140
NVRAM	Memory IC	U2040
Presampler	Presampler Hypcon IC	U650
Diode Bridge	Diode Bridge Hypcon IC	U950
SDI	Serial Data Interface IC	U1540
Attenuator	Attenuator assembly	
CAL Relay	CH 1 Cal Relay	
Fuse	External Trigger Fuse	F330

Table 3-2 — Component/Module FRUs

Error Index Codes

The error index codes are divided into three tables. A table of Kernel error index codes (Table 3-3), a table of Self Tests/Extended Diagnostic error indexes (Table 3-4), and a table of Enhanced Accuracy error indexes (Table 3-5).

Table 3-3 lists the error codes possible in the Kernel Tests.

Table 3-3 - Amplifier Kernel Error Index Codes

Error Code (# of CH 1 LED Lightings)	Suspect Module, Hybrid, or IC FRU(s)	Suspect Board (FRU(s)
1	EPROM	Main
2	NVRAM	Main
3	SDI	Main

Table 3-4 lists the error codes possible for the Self Tests and Extended Diagnostics.

Table 3-4 - Self Tests/Extended Diagnostics Error Index Codes

Error Code	Suspect Module, Hybrid, or IC FRU(s)	Suspect Board (FRU(s)
1111	NVRAM	Main
1121	NVRAM	Main
1131	(mainframe)	Main
1141	Probe	Main
1151		Main, S/H1, S/H2
1211		Main
1221	(Probe power)	Main, Probe
1231		Main
1241		Main
1311	SDI	Main, S/H1, S/H2
1321		RMS Pickoff, Main
1611	Presampler	Main
1621	Presampler, Diode Bridge, Attenuator	Main

Note: Interconnections are not listed but you should consider them as possible problem sources.

Table 3-5 lists the error codes possible from Enhanced Accuracy calibration. Other error codes may be generated for other installed plug-in units or the oscilloscope mainframe.

Table 3-5 — Enhanced Accuracy Error Index Codes

Error Code	Suspect Module, Hybrid, or IC FRU(s)	Suspect Board (FRU(s)
1411	Presampler	Main
1421	Pesampler	Main
1431	Attenuator	
1441	Pesampler	Main
1451	Pesampler	Main
1461	Pesampler, Diode Bridge	Main
1471	Diode Bridge	Main

Decoding an S/H Failure

You can decode the **Actual** data accompanying an X1311 error code to identify the suspect Sample and Hold board. The **Actual** data is a hexadecimal (hex) number. Convert this hex number to binary, then determine which bits are 1. For example, the hex code 0040 is equivalent to the binary 0000 0000 0100 0000. The single 1 is in Binary Bit position 6 which points to the S/H2 board.

Table 3-6 shows the suspect board and the board pin number for the failed ACVS channel. Refer to Figure 3-1 to locate a failed S/H board. If both S/H boards have failures this would point to the SDI IC or other common circuitry.

Table 3-6 — Sample and Hold Board Failure Codes

Binary Bit	Suspect S/H FRU	Board Pin #
15	S/H2 (J1570)	20
14	S/H2	22
13	S/H1 (J1580)	20
12	S/H1	22
11	S/H2	19
10	S/H2	23
9	S/H1	19
8	S/H1	23
7	S/H2	17
6	S/H2	14
5	S/H1	17
4	S/H1	14
3	S/H2	15
2	S/H2	16
1	S/H1	15
0	S/H1	16

Refer to Table 3-5 for a list of error indexes resulting from Enhanced Accuracy.

Fuse Troubleshooting

The fuse F330 protects the External Trigger circuit. Figure 3-1 (FRU locator) shows the location of fuse F330 and the on board spare fuse. To remove the fuse, press down on both ends of the fuse metal spring and slide the spring until it pops up. Remove the metal spring and the fuse. If the fuse has zero resistance across the two contacts on the bottom center of the fuse, it is good.

Diagnostic error code 1221 indicates that one or more of the probe power lines appear defective. Both the CH 1 and EXTERNAL TRIGGER INPUT provide probe power. Check probe connections and/or remove the probes and rerun the failed diagnostic test. Check the flexible cables connecting the TEKPROBE connectors to the Main board for continuity. A continued failure with no probe attached indicates a possible Main board problem.

Jumpers

The Main board has three jumpers as shown on Figure 3-1. The jumpers are as follows:

- J1630 (default 2-3) configures the 11A81 to allow the plug-in unit ID and factory calibration constants to be modified.
- J1970 (default 2-3) configures the MPU to read from the EPROM.
- J2180 (default 2-3) configures the MPU for reset.

Corrective Maintenance

Corrective maintenance consists of Field Replaceable Unit (FRU) and FRU IC replacement. This section describes the techniques required to replace the FRUs in the 11A81.

Ordering Parts

For instructions on how to order replacement parts, refer to *Replaceable Parts*, section 5 of this manual.

Static-Sensitive Device Classification



Static discharge can damage any semiconductor in the amplifier.

The amplifier contains electrical components that are susceptible to damage from static discharge. Refer to Table 3-7, Relative Susceptibility to Damage from Static Discharge, for the relative susceptibility of various classes of semiconductors. Static voltages of 1 kV to 30 kV are common in unprotected environments.

Observe the following precautions to avoid damage:

- 1. Minimize handling of static-sensitive components.
- Transport and store static-sensitive components or assemblies in the original containers if possible; otherwise transport them on a metal surface or conductive foam. Label any package that contains static-sensitive assemblies or components.

- 3. Wear a wrist strap while handling these components to discharge the static voltage from your body. Servicing static-sensitive assemblies or components should be performed only at a static-free work station by qualified service personnel. Use a static control mat during repair.
- Clear anything from the work station surface that is capable of generating or holding static charge.
- 5. Keep the component leads shorted together when not installed.
- 6. Pick up components by the body, never by the leads.
- 7. Do not slide components over any surface.
- 8. Avoid handling components in areas that have a floor or a work-surface covering that is capable of generating static charge.

Table 3-7 — Relative Susceptibility to Damage from Static Discharge

Semiconductor Classes	Relative Susceptibility Levels
MOS or CMOS microcircuits, and discrete or linear microcircuits with MOS inputs (most sensitive)	1
ECL	2
Schottky signal diodes	3
Schottky TTL	4
High-frequency bipolar transistors	5
JFETS	6
Linear microcircuits	7
Low-power Schottky TTL	8
TTL (least sensitive)	9

¹Voltage equivalent for levels.

1 = 100 to 500 V 6 = 600 to 800 V 2 = 200 to 500 V 7 = 400 to 1000 V (est.)

3 = 250 V 8 = 900 V 4 = 500 V 9 = 1200 V

5 = 400 to 600 V

(The voltage equivalent is the voltage discharged from a 100 pF capacitor through a resistance of 100 Ω .)

Removing/Replacing FRUs

Table 3-8, FRU Removal/Replacement Procedures, lists the procedures that describe how to remove and replace the FRUs. The first column in the table lists the FRU to be removed or replaced, and the second column lists the procedures that you should follow to remove/replace this FRU. See Figure 3-1 to determine the location of an FRU.

CAUTION

To avoid damage to the amplifier, set the oscilloscope's ON/ STANDBY switch to STANDBY, and remove the amplifier from the oscilloscope before removing or replacing FRUs.

CAUTION

If the oscilloscope's green indicator light remains lit when the ON/ STANDBY switch is in the STANDBY position, then the switch was internally disabled after the servicing of the Power Supply module. To enable the ON/STANDBY switch, refer to Section 3, Maintenance, of the Service Reference manual for your oscilloscope.

The exploded-view drawing in Section 5, Replaceable Parts, may also be useful in the removal/replacement procedures that follow. Note that the side shields will have to be removed to gain access to most of the parts listed in the removal/replacement procedures that follow.

Table 3-8 – FRU Removal/Replacement Procedures

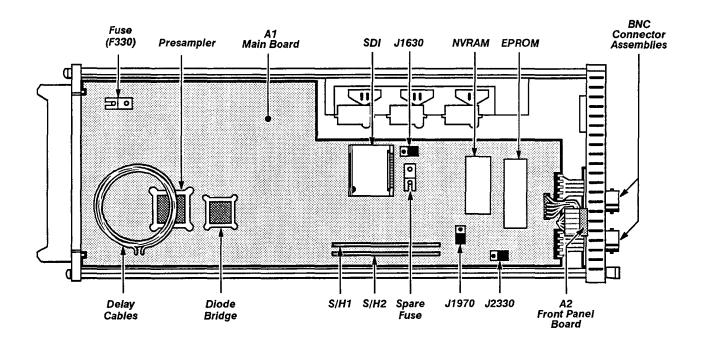
FRU to be Replaced	Procedures to Reference During Removal/Replacement	Page
A2 Front Panel board	Removing/Replacing the Front Panel Assembly	3-20
BNC Connectors	Removing/Replacing the Front Panel Assembly	3-21
Cal Relay	Removing/Replacing the Cal Relay	3-22
RMS Pickoff	Removing/Replacing the RMS Pickoff board	3-23
Attenuator	Removing/Replacing the Attenuator	
A1 Main Board	Removing/Replacing the A1 Main Board	3-28 3-38
Heat Sink	Removing/Replacing the A1 Main Board Removing/Replacing the Heat Sink Removing/Replacing Hypcon Assemblies	3-28
Presampler Hypcon (U1540)	Removing/Replacing Hypcon Assemblies	3-29

3-14 Corrective Maintenance

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Table 3-8 — FRU Removal/Replacement Procedures

FRU to be Replaced	Procedures to Reference During Removal/Replacement Pa	ge
Diode Bridge Hypcon (U950)	Removing/Replacing Hypcon Assemblies 3-	-29
SDI (U1540)	Removing/Replacing the Serial Data Interface (SDI) IC (U1540) 3-	-33
NVRAM (U2040)	Removing/Replacing the NVRAM IC	
EPROM (U2140)	Removing/Replacing the EPROM IC	-35



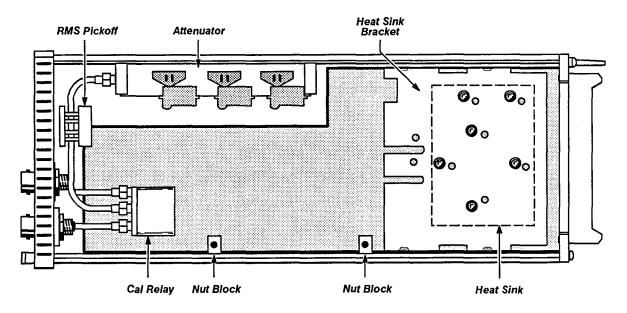
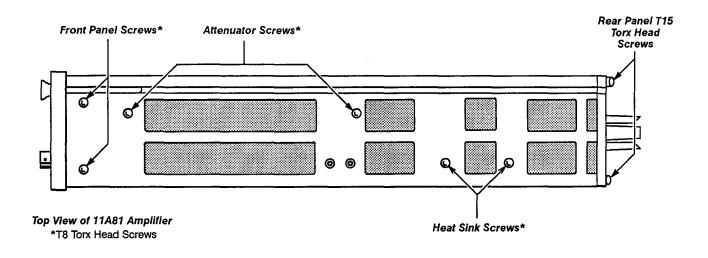


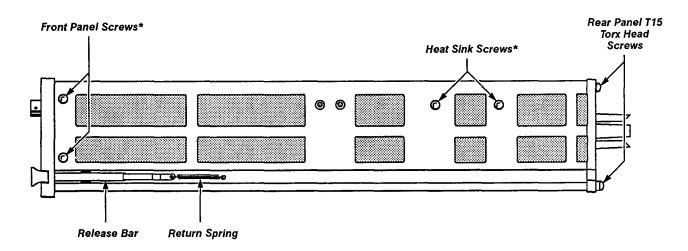
Figure 3-1 - FRU and FRU IC Locator

Removing/Replacing the Front Panel Assembly

The Front Panel assembly must be removed to gain access to several replaceable FRUs and mechanical parts. The Cal Relay and its bracket are removed with the Front Panel assembly. You will need a $\frac{6}{16}$ open end wrench for this procedure. See Figures 3-1, 3-2 and 3-3 for connector and screw locations.

Rer	move the Front Panel assembly as follows:
	Step 1: Unhook the return spring, located on the bottom of the amplifier, from the bottom frame. Keep this spring for reassembly.
	Step 2: Carefully pull the coaxial cable from the rear of the EXTERNAL TRIG- GER INPUT Peltola connector.
	Step 3: Loosen the two Pozidrive #1 tip screws on the Cal Relay.
	Step 4: Using a 5/16" open end wrench, disconnect the RMS Pickoff board from the Cal Relay as follows:
	 Disconnect the SMA cable from the N0 connector (nearest plug-in center) on the Cal Relay.
	■ Loosen the SMA connector on the front of the Attenuator.
	■ Disconnect the SMA cable from the middle connector on the Cal Relay.
	■ The RMS Pickoff board will be loose but still connected to the Attenuator by SMA cable and to the Main board by its two-wire cable when you remove the Front Panel assembly.
	Step 5: Turn the plug-in so the component side faces you. Disconnect the multi-pin connector that comes from the A2 Front Panel board at the A1 Main board. Note the position of the multi-pin connector index triangle to ensure correct replacement.
	Step 6: Disconnect the probe-information connectors from the A1 Main board as follows:
	■ Place your index finger under the metal contacts with your thumb on top.
	Starting at one end, lift the seven metal contacts out of the receptacle on the A1 Main board.
	Step 7: Remove the T10 Torx head screw that secures the Cal Relay bracket to the A1 Main board. The screw is located next to the connector J2440 at the front of the A1 Main board.





Bottom View of 11A81 Amplifier

*T8 Torx Head Screws

Figure 3-2 - Removing/Replacing the Front Panel

- Step 8: Remove the four flat-head, T8 Torx head screws (two on the bottom and two on the top of the front panel) that secure the front panel to the top and bottom frames.
- Step 9: Pull the release bar out of the front subpanel as far as possible. Leave the release bar in this position.
- Step 10: Pull the Front Panel assembly loose from the plug-in, taking care to clear the RMS Pickoff board. Figure 3-3 shows the complete Front Panel assembly.

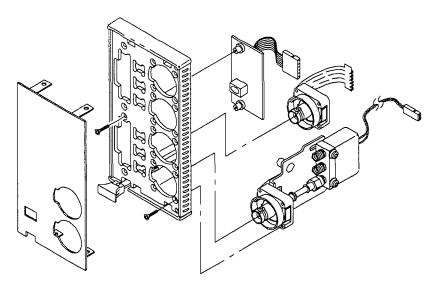


Figure 3-3 — Components of the Front Panel Assembly

Ш	Front Panel tabs at the top and bottom where they fit through holes in the front subpanel.
	Step 12: Carefully separate the Front Panel from the subpanel and remove the Front Panel from the Front Panel assembly. Take care not to bend the Front Panel.
	Step 13: Reinstall the Front Panel assembly by performing in reverse order Steps 1 through 12. Do not over tighten the SMA connectors as this could degrade product bandwidth. Before tightening the Cal Relay Pozidrive® screws, press the Cal Relay fully forward to ensure proper mating of the CH 1 Peltola connector.

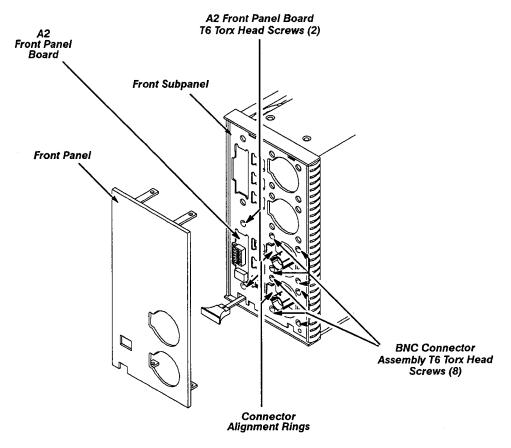


Figure 3-4 — Removing/Replacing the BNC Connector Assembly and the A2 Front Panel Board

Removing/Replacing the A2 Front Panel Board

See Figures 3-1, 3-3, 3-4, and 3-12 for connector, screw and index locations.

Remove and replace the A2 Front Panel board as follows:

	•
Step 1:	Remove the Front Panel assembly as described on page 3-17.
•	Remove the two T6 Torx head screws that secure the A2 Front Panel the front subpanel.
Step 3:	Remove the A2 Front Panel board.

Step 4: Replace the A2 Front Panel board by performing in reverse order Steps 1 through 3.

Corrective Maintenance

Removing/Replacing the BNC Connector Assemblies

The procedures needed to remove the two BNC connectors are somewhat different. You will need to remove the Front Panel assembly to gain access to either BNC. These BNC connectors are unique in that their back ends have Peltola connectors. See Figures 3-1, 3-2, 3-3, 3-4 and 3-12.

Remove the BNC connector assemblies as follows:		
		Remove the Front Panel assembly including the Front Panel as de- on page 3-17.
	secure t	For the CH 1 BNC only, <i>loosen</i> the two Pozidrive #1 tip screws that he Cal Relay to its bracket. For the EXTERNAL TRIGGER INPUT BNC or proceed to Step 6.
	Step 3:	Loosen the SMA connector on the short, rigid coaxial cable.
	Step 4: CH 1 rig	Slide the Cal Relay away from the Front Panel as needed to remove iid coaxial cable.
	Step 5: connect	Carefully pull the short, rigid coaxial cable straight out of the CH 1 or and set it aside. Do not bend the center conductor.
	Step 6: back of	Remove the nut and washer securing the Cal Relay bracket to the the CH 1 connector and remove the Cal Relay with bracket.
	•	Remove the four T6 Torx head screws that secure the BNC connector ly to the front subpanel.
	Step 8:	Remove the BNC connector assembly from the front subpanel.
Replace the BNC connector assembly as follows:		
	ring's in	Set the gray connector alignment ring on the BNC connector with the dex on the inside of the connector assembly (that is, the side where cable enters the connector assembly).
	hole in t	Insert the BNC connector and the connector alignment ring into the he front subpanel. Ensure that the flat cable is oriented towards the f the amplifier and the index on the connector alignment ring fits into the front subpanel.
		Replace the four Torx head screws that secure the connector asseme front subpanel.
		For the CH 1 BNC, reconnect the Cal Relay bracket to the back of 1 BNC using the nut and washer.
	connect	Carefully insert the short, rigid coaxial cable into the CH 1 Peltola or, then slide the Cal Relay forward and connect the SMA connector. that the coaxial cable is fully seated in the Peltola connector.
	Step 6:	Replace the Front Panel assembly as described on page 3-17.

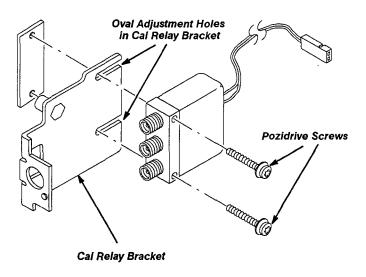


Figure 3-5 — Removing/Replacing the Cal Relay

Removing/Replacing the Cal Relay

See Figures 3-1, 3-3, 3-5 and 3-12 for connector, screw, and index locations.

Remove and replace the Cal Relay as follows:

- Step 1: Loosen the two Pozidrive #1 tip screws that secure the Cal Relay to its bracket, but do not remove them. Step 2: Using the 5/6" open end wrench, loosen the SMA connector from the Cal Relay connector nearest to the plug-in center. Step 3: Remove the two-wire cable from J1100 on the Main board. Step 4: When the SMA rigid cable is free but still fully seated in the back of the CH 1 connector, slide the Cal Relay back until it is free of the bracket.
- Step 5: Reinstall the Cal Relay by performing in reverse order Steps 1 through 4. If you are replacing the Cal Relay the red wire goes toward the label sided of the Cal Relay. When the Cal Relay is installed, the brown wire will be further away from the Main board than the red wire and will connect to pin 1 of J1100. Be certain that the CH 1 SMA cable is fully seated in the CH 1 Peltola connector.

	Removing/Replacing the RMS Pickoff board
	See Figure 3-1 for connector, screw, and index locations.
	Remove the RMS Pickoff board as follows:
	Step 1: Loosen the Cal Relay Pozidrive #1 tip screws.
	Step 2: Remove the coaxial cable from the rear of the EXTERNAL TRIGGER INPUT.
	Step 3: Using the ⁵ / ₁₆ " open end wrench, loosen the SMA connectors from the Cal Relay connector nearest to the plug-in center and from the center con- nector.
	Step 4: Remove the RMS Pickoff cable from the Attenuator.
	Step 5: Carefully note the orientation of the wire connections from the Pick- off board to the Main board, then desolder the wires at the Main board. Re- move the RMS Pickoff board.
	Step 6: Reinstall the RMS Pickoff board by performing in reverse order Steps 1 through 5. Note that the RMS Pickoff board will fit one way only; with the shorter, rigid-coaxial-cable toward the Attenuator. The signal lead (brown) connects to Pin 1 (the square pad) on the Main board.
	Removing/Replacing an Attenuator
	In this procedure, you will remove the top rail with the Attenuator attached. Read the following cautions before proceeding with the procedure.
CAUTION	Applying excessive stress to the Z-shaped rigid coaxial cable at the rear of the Attenuator can ruin the Main board. The Z-shaped rigid coaxial cable is designed to flex enough to allow SMA connections during Attenuator removal.
ECAUTION §	When reconnecting the SMA rigid cables, do not over tighten the connectors. Doing so can damage the connector gasket and distort the cable dielectric, which can degrade the high-frequency performance of the cable.
	See Figures 3-1 and 3-2 for connector and screw locations.
	Remove and replace the Attenuator as follows:
	Step 1: Pull the SMA cable free from the Peltola connector at the back of the EXTERNAL TRIGGER INPUT.
	Step 2: Remove the Attenuator ribbon cable from J1000.
	Step 3: Using the ¾6" open end wrench, remove the SMA cable from the Cal Relay connector nearest the plug-in center, and then loosen the SMA connector on the center connector.
	Step 4: Loosen the SMA connectors at each end of the Attenuator.

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plug-in u	Remove the T8 Torx head screws that secure the side rail to the unit, but do not remove the two screws that secure the Attenuator to rail. See Figure 3-2.
Step 6: the top s	Remove the two T15 Torx head screws that secure the Rear panel to side rail.
•	Disconnect the SMA connector from the front of the Attenuator using k gained by loosening the middle SMA connector on the Cal Relay.
•	Lift up on the side rail while you remove the Z-shaped rigid coaxial om the Attenuator. Remove the side rail and Attenuator from the plug-
•	Remove the two T8 Torx head screws that secure the Attenuator to rail and remove the Attenuator.
•	If you are replacing the Attenuator remove the four T10 Torx head that secure the bracket to the Attenuator.
•	Reinstall the Attenuator by performing in reverse order Steps 1 10. Ensure that all SMA connectors are properly tightened.
•	ement of the Attenuator, you should perform the Checks and Adjust- dures 1 through 3.

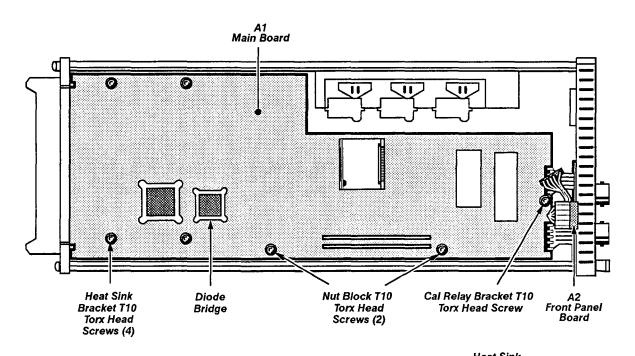
3-24 Corrective Maintenance

Removing/Replacing the A1 Main Board

The Main board contains a number of FRU ICs whose replacement is described later in this section. Refer to Table 3-8 on page 3-14 for the locations of these procedures. See Figures 3-1, 3-2, 3-8, 3-6, 3-7, and 3-12 for connector, screw, and index locations.

Rer	nove and	replace the A1 Main board as follows:
	Panel bo	Disconnect the multi-pin connector that connects from the A2 Front pard to the A1 Main board. Note the position of the multi-pin connect triangle to ensure that this connector can be correctly replaced.
	•	Disconnect the probe information connectors from the A1 Main s follows:
	■ Plac	e your index finger under the metal contacts with your thumb on top.
		ting at one end, lift the seven metal contacts out of the receptacle on A1 Main board.
	and Cal	Disconnect the multi-pin connectors that connect from the Attenuator Relay to the A1 Main board. Note the position of the multi-pin condex triangle to ensure that this connector can be correctly replaced.
	TERNAL J1130, re	Carefully remove the two coaxial cables that connect from the EX- TRIGGER INPUT and Cal Relay to the Peltola connectors J420 and espectively. Pull straight up on the cables to keep from bending the onductors. Note where each cable connects.
	Step 5:	Loosen the SMA connector at the rear of the Attenuator.
	Step 6: A1 Main	Remove the T10 Torx head screw that secures the Cal Relay to the board.
		Remove the four T15 Torx head screws that secure the plastic rear the top and bottom frames.
	•	Remove the four T8 Torx head screws that secure the heat sink to the top and bottom frames.
	•	Remove the two T10 Torx head screws and nut blocks that secure fain board to the bottom frame.
		As you slide the A1 Main board between the frames and out the connect the SMA cable from the rear of the Attenuator. Try to minimize the Z-shaped rigid coaxial cable that remains on the A1 Main board.
	A1 Main rear-pan stall the	If you are replacing the Main board, you will need to remove the ables and IC Heat Sink bracket (described on page 3-27) from the old board and install them on the new A1 Main board. Also, press the el lock pin out of the alignment hole in the A1 Main board and reinplastic rear panel on the new Main board. Do not remove the Prestypcon IC from the old Main board.
	through	Reinstall the A1 Main board by performing in reverse order Steps 1 10. Do not over tighten the SMA connector as this can adversely afhigh-frequency performance.

Step 13: If the A1 Main board has been replaced, then you will need to reenter the Unit Identification (UID) number. Refer to *Programming the Unit Identification and Calibration Constants* on page 3-36.



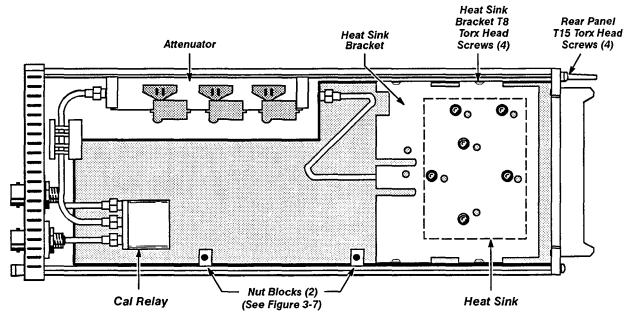


Figure 3-6 — Removing/Replacing the A1 Main Board

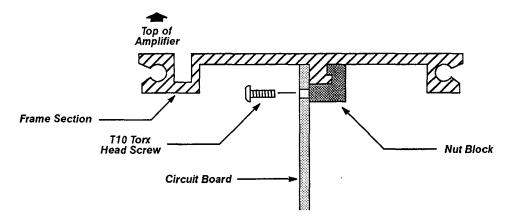
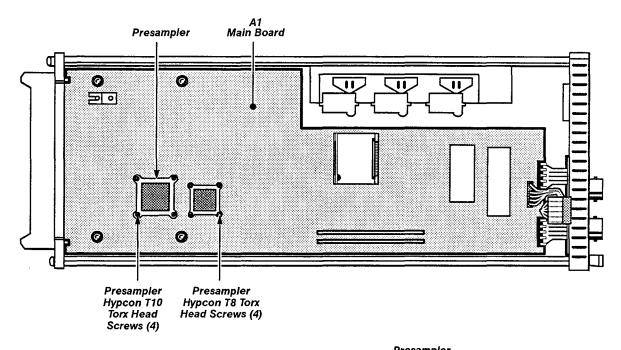


Figure 3-7 — Torx Screw and Nut Block Orientation

Removing/Replacing the Presampler Heat Sink

To access the Presampler heat sink, you must first remove the A1 Main board and then the heat sink bracket as described in the following procedure. The heat sink bracket and heat sink require thermal grease between them to ensure proper cooling of the Presampler IC. Refer to the Test Equipment list on page 2-3 for information on the recommended type of thermal grease. See Figures 3-1, 3-8 and 3-9 for screw and index locations.

Remove and replace the heat sink as follows:
Step 1: Remove the A1 Main board as described on page 3-25.
Step 2: From the heat sink, remove the six T10 Torx head screws that secure the heat sink bracket to the A1 Main board and heat sink. See Figure 3-8.
Step 3: From the component side of the A1 Main board, remove the four T10 Torx head screws that secure the heat sink bracket to the A1 Main board.
Step 4: Lift up on the heat sink bracket and remove it from the A1 Main board. Take care not to spread thermal grease to components that do not require it.
Step 5: Remove the Presampler Hypcon assembly as described on page 3-29. (This need not be removed if the Main board is being replaced.)
Step 6: Remove the Presampler heat sink.
Step 7: Reinstall the Presampler heat sink by performing Steps 1 through 6. Spread a thin layer of thermal grease on the Presampler heat sink before installing the heat sink bracket.



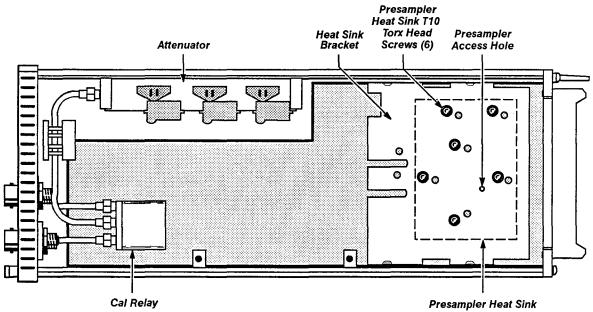


Figure 3-8 — Removing/Replacing the Presampler Heat Sink

CAUTION

Observe all the special precautions mentioned under Static-Sensitive Device Classification earlier in this section.

Removing/Replacing Hypcon Assemblies

The 11A81 Main board contains two Hypcon (Hybrid-printed circuit connector) ICs: the Presampler (U650) and the Diode Bridge (U950). Replacement procedures for the two ICs is similar though some extra steps are necessary to ensure proper application of thermal grease for the Presampler IC. The Diode Bridge does not require thermal grease. The Diode Bridge procedure follows the Presampler IC procedure.

Figure 3-9 shows two views of the Hypcon assembly and identifies the parts of a Hypcon assembly. When replacing a Hypcon IC do not touch the elastomer's gold-plated contacts with your fingers. The Hypcon socket contacts are fragile and easily fouled by oil and dirt.

When removing and replacing a Hypcon follow these precautions:

- Clean contaminated hybrid and elastomer contact holders by flushing or spraying them with alcohol. If the contact holder is excessively contaminated, replace the holder.
- Use a 4X magnifying glass to examine the hybrid, elastomer, and the Hypcon contacts for dust, hair, lint, heat-transfer grease or other foreign matter. If the A1 Main board surfaces require more cleaning, then lightly scrub the surface with a soft rubber eraser and then clear any residue with low pressure air or vacuum while dusting the surface with a clean brush.

CAUTION

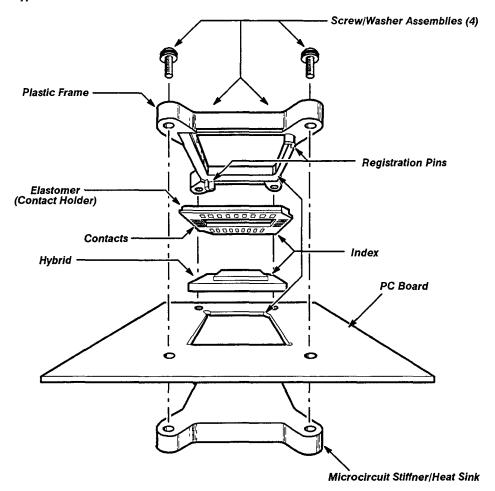
Do not scrub with a cotton-tipped swab or similar device, since cotton fibers may adhere to the contacts.

- The Presampler IC requires thermal grease between the IC and its heat sink and between the heat sink and the heat sink bracket. The thermal grease should be kept off all hypcon contacts. To remove any thermal grease from the contacts, flush or spray them with alcohol.
- Ensure that the elastomer is properly seated in the contact holder before remounting the assembly to the A1 Main board. That is, use care when mounting the assembly to the board to ensure that the proper alignment exists between the connector and A1 Main board.

CAUTION

Special care must be taken to ensure correct index alignment of each Hypcon part during reassembly. Failure to do so can result in a cracked hybrid substrate.

Exploded View of Hypcon Connector



Cross Section View of Hypcon Connector

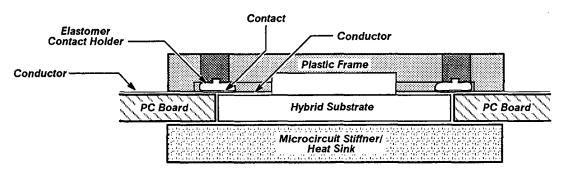


Figure 3-9 — Removing/Replacing a Hypcon Assembly

Presampler Hypcon (U650) Removal — See Figure 3-1 for component identification, Figure 3-9 for indexing information and Figure 3-8 for Presampler Heat Sink information. Refer to the Test Equipment list on page 2-3for information on the recommended type of thermal grease.	
Remove the Presampler IC as follows:	
Step 1: Notice the index on the A1 Main board (arrow) and the plastic frame (pointed tab).	
Step 2: Unscrew and remove the four T10 Torx head screws with washers.	
Step 3: Lift the plastic frame from the A1 Main board.	
Step 4: Notice the index location of the hybrid.	
For the next Step you will need a 5-10 mm rod and a pair of tweezers to remove the Presampler hybrid IC.	
Step 5: Insert a 5–10 mm rod through the special hole in the Heat Sink bracket (see Figure 3-8) and apply steady, firm pressure on the back on the Presampler hybrid. The Presampler is held in place by adhesion of the thermal transfer grease between it and its heat sink	
Step 6: When the Presampler is free, remove it from A1 Main board with the tweezers.	
Note: Step 7 describes the removal of the elastomer from the plastic frame. This step is unnecessary when replacing the hybrid only.	
Step 7: Notice the index location of the elastomer (contact holder). Grasp and lift the corner of the contact holder with the tweezers to remove the holder from the plastic frame. (Do not touch the gold-plated contacts with your fingers.)	
Ensure all parts are clean as described above, then replace the Presampler hypcon as follows:	
Step 1: Grasp a corner of the elastomer with the tweezers, and place the elastomer into the plastic frame.	
Step 2: Align the keyed corner of the elastomer with the keyed corner of plastic frame.	
Step 3: Tamp the elastomer into the plastic frame uniformly.	
Note: Keeping the elastomer clean is very important. Small hairs and elastomer flash under the contacts can be almost impossible to see, but they can prevent good electrical contact. Most apparent failures of the hybrid are actually due to contamination of the Hypcon. Therefore, do not touch the gold-plated contacts with your fingers.	
Step 4: Apply a small amount of thermal grease (a spot approximately $\frac{1}{16}$ inch or 5 mm in diameter) to the bottom, center of the Presampler IC. Applying excessive grease will result in fouled Hypcon contacts.	

	Step 5: Carefully place the hybrid into the square hole in the A1 Main board. The hybrid is keyed so that it will fit into the A1 Main board in only one orientation. When the back of the hybrid rests on the heat sink pedestal, the top of the hybrid should be flush with the top of the A1 Main board. Take care not to get thermal grease on the IC contacts located on the Main board.							
	Step 6: Place the plastic frame, with the elastomer installed over the hybrid so that the key (pointed tab) aligns with the corner arrow on the board.							
	Step 7: Replace the four Torx head screws with washers, and apply two inch-pounds of torque, (2.3 cm-kg) to secure the connector assembly. Do not overtighten the assembly; doing so can strip the microcircuit stiffener/heat sink mounting threads.							
Diode Bridge Hypcon (U950) Removal — See Figure 3-9 for indexing information, and see Figure 3-1 for component identification.								
Rer	nove the Diode Bridge Hypcon as follows:							
	Step 1: Notice the index on the A1 Main board (arrow) and the plastic frame (pointed tab).							
	Step 2: Unscrew and remove the four T8 Torx head screws with washers.							
	Step 3: Lift the plastic frame from the A1 Main board.							
	Step 4: Notice the index location of the hybrid and remove the hybrid from the A1 Main board with tweezers.							
	Note: Step 5 describes the removal of the elastomer from the plastic frame. This step is unnecessary when replacing the hybrid only.							
	Step 5: Notice the index location of the elastomer (contact holder). Grasp and lift the corner of the contact holder with the tweezers to remove the holder from the plastic frame. (Do not touch the gold-plated contacts with your fingers.)							
	ure all parts are clean as described above, then replace the Diode Bridge con as follows:							
	Step 1: Grasp a corner of the elastomer with the tweezers, and place the elastomer into the plastic frame.							
	Step 2: Align the keyed corner of the elastomer with the keyed corner of plastic frame.							
	Step 3: Tamp the elastomer into the plastic frame uniformly.							
	Note: Keeping the elastomer clean is very important. Small hairs and elastomer flash under the contacts can be almost impossible to see, but they can prevent good electrical contact. Most apparent failures of the hybrid are actually due to contamination of the Hypcon. Therefore, do not touch the gold-plated contacts with your fingers.							

3-32

	Step 4: Carefully place the hybrid into the square hole in the A1 Main board. The hybrid is keyed so that it will fit into the A1 Main board in only one orientation. When the back of the hybrid rests on the heat sink pedestal, the top of the hybrid should be flush with the top of the A1 Main board.							
	Step 5: Place the plastic frame, with the elastomer installed over the hybrid, so that the key (pointed tab) aligns with the corner arrow on the board.							
	Step 6: Replace the four Torx head screws with washers, and apply two inch-pounds of torque, (2.3 cm-kg) to secure the connector assembly. Do not overtighten the assembly; doing so can strip the microcircuit stiffener/heat sink mounting threads.							
	Removing/Replacing the Serial Data Interface (SDI) IC (U1540)							
	The Serial Data Interface IC (U1540) is indexed to its socket by a beveled corner. The other corners are notched to fit the edges of the socket. The beveled corner aligns with a spring (small metal tab) at one corner of the socket.							
	See Figure 3-1 for component identification an 3-10 for indexing information.							
	Remove the Serial Data Interface IC as follows:							
	Step 1: To remove the retaining clip, press down on the metal cover while you move the retaining clip over the tabs.							
	Step 2: Slowly remove the cover to prevent the IC from falling out. Note the position of the index on the IC to ensure that this IC can be correctly replaced.							
	Step 3: Remove the IC with clean tweezers.							
CAUTION	Avoid touching the IC or the socket contacts with your fingers since finger oils can lessen reliability.							
	Replace the Serial Data Interface IC as follows:							
	Step 1: Using tweezers, place the beveled corner of the replacement IC against the index spring.							
ECAUTION }	Do not damage the spring with the beveled corner; this could cause a short in the two corner contacts.							
	Step 2: Arrange the other corners, with the tweezers, to fit evenly at the edges of the socket.							
	Step 3: Set the cover flat on the IC with the cover's end tabs properly aligned with, but not in, the mating recesses of the socket.							
	Step 4: Push the cover down, keeping the cover flat on the IC, and slide the cover end tabs into place. Then, hold the cover in place while moving the retaining clip over the tabs on the other end of the cover.							

11A81 Service Reference 3-33

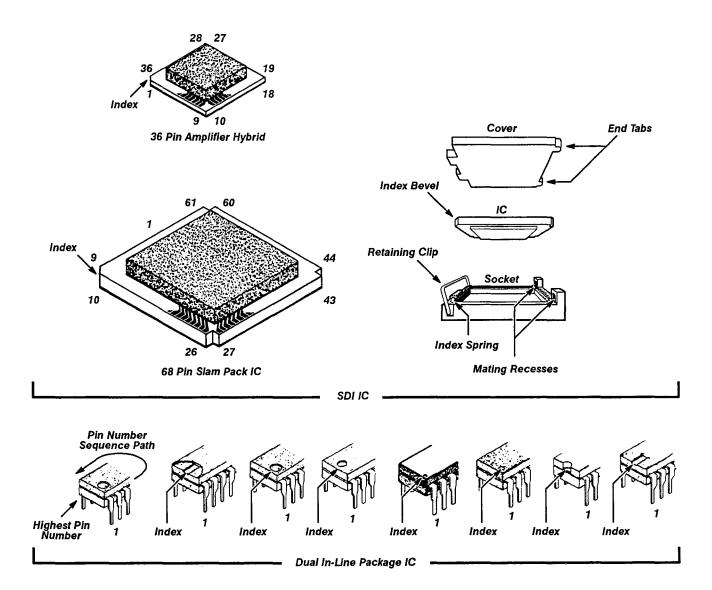


Figure 3-10 - Semiconductor Indexing Diagram

Removing/Replacing the NVRAM IC

The NVRAM IC (U2040) is located on the A1 Main board. Important calibration information and the serial number for your 11A81 are stored in the NVRAM. You must put this information into the new NVRAM.

See Figure 3-1 for component identification and 3-10 for indexing information.

If the NVRAM IC is soldered into the board, then consult a Tektronix service center for recommended removal procedures. Do not solder-in the replacement IC: Instead, install a high quality 24-pin socket, and insert the new NVRAM IC into this socket. Follow the procedure on page 3-36 to record this data. Then perform the Procedures 1 through 3 in the Checks and Adjustments section of this manual.

3-34 Corrective Maintenance

Removing/Replacing the EPROM IC

The EPROM IC (U2140) is located on the A1 Main board. You might need to change this IC if the EPROM develops a problem or if you are upgrading the firmware.

CAUTION

Do not remove the label affixed to the top of the EPROM. Removing this label will allow light into the IC, and can result in data in this IC being erased.

CAUTION

Avoid touching the IC pins or socket contacts with your fingers. Finger oils can lessen contact reliability.

See Figures 3-1, 3-10 and 3-11 for location, equipment and indexing information.

Remove the EPROM IC as follows:

- Step 1: Use the insertion-extraction pliers to remove the IC.
- Step 2: Position the pliers around the outside of the IC. Squeeze the handles to grasp the IC, and slowly pull the IC from the socket.

Replace the EPROM IC as follows:

- Step 1: Grasp the IC with the insertion-extraction pliers; ensuring that all the pins of the IC are straight and evenly spaced. (Do not use the IC label as an index, instead locate the index on the body of the IC.)
- Step 2: Align the index slot with the corresponding index on its socket.
- Step 3: Align the pins with their respective socket contacts.
- Step 4: Press the IC slowly and evenly into its socket.

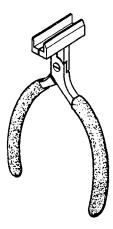


Figure 3-11 - IC Insertion-Extraction Pliers

11A81 Service Reference 3-35

Programming the Unit Identification and the Calibration Constants

If you replace the nonvolatile RAM (NVRAM) or the A1 Main board; or the if the calibration constants are corrupted due to a power down of the oscilloscope during Enhanced Accuracy calibration, you will need to perform one of the following procedures. Jumper settings described in the procedures are not needed if you want only to query the current UIDs or calibration constants.

the ser	NVRAM	and the Unit Identification — The Unit Identification (UID) is stored in and is identical to the serial number of the amplifier. You can find the er at the front of the top rail of the 11A81. Program the UID into the follows:					
	Step 1:	Connect a terminal to the RS-232-C port of the oscilloscope.					
	Step 2:	Set the oscilloscope RS232C parameters as follows:					
	■ Pres	ss the UTILITY button twice, and then touch RS232C.					
	■ Set	the Baud Rate to match the baud rate of the terminal you are using.					
	■ Set	Echo to On and Verbose to On.					
		er to your oscilloscope <i>User Reference</i> for additional information on figuring the RS-232-C port.					
		Configure your mainframe by setting the calibration jumper J450 on time Base board. Refer to your mainframe Service Reference for the location.					
		tep 4: Set the jumper J1630 across Pins 1 and 2 on the 11A81 A1 Main oard. See Figure 3-1 for the jumper location. Obtain the amplifier serial numer from the printed tag on the amplifier top rail, near the front panel.					
	Step 5:	Place the amplifier in any compartment.					
	Step 6:	Set the ON/STANDBY switch to ON.					
	Step 7:	Wait until the Diagnostics checks are completed.					
	Step 8:	On the Terminal, enter the command:					
	UID [Le	ft Center Right]:" <serial number="">"</serial>					
	•	r Right refers to the compartment in which the amplifier resides. The per should include the initial character, usually B.					
	Step 9:	On the terminal, verify the entry by entering the query:					
	UID? [Left Center Right]						
	Observe	e that the correct UID is reported.					
	Step 10	Set the ON/STANDBY switch to STANDBY.					
	Step 11:	Remove the amplifier.					

3-36 Corrective Maintenance

Step 12: Return the jumpers J1630 on the 11A81 Main board and J450 on the oscilloscope Time Base board to their normal operation positions.
If you need only confirm the UID, then you can skip Steps 1, 2, 6 and 10.
Programming the Calibration Constants — The calibration constants set the correct bias for the high-frequency signal path. There are five calibration constants to enter. Program the calibration constants as follows:
Step 1: Connect a terminal to the RS-232-C port of the oscilloscope.
Step 2: Set the oscilloscope RS232C parameters as follows:
Press the UTILITY button twice, and then touch RS232C.
Set the Baud Rate to match the baud rate of the terminal you are using.
Set Echo to On and Verbose to On.
Refer to your oscilloscope User Reference for additional information on configuring the RS-232-C port.
Step 3: Configure your mainframe by setting the calibration jumper J450 on the A6 Time Base board. Refer to your mainframe Service Reference for the jumper location.
Step 4: Set the jumper J1630 across Pins 1 and 2 on the 11A81 A1 Main board. See Figure 3-1 for the jumper location.
Step 5: Place the amplifier in the CENTER compartment.
Step 6: Set the ON/STANDBY switch to ON.
Step 7: Wait until the Diagnostics checks are completed.
Step 8: The following commands assume the 11A81 is installed in the CENTER compartment. If the 11A81 is installed in the LEFT or RIGHT compartment use the command LCA: or RCA:, respectively. On the terminal, enter each calibration constant as shown:
CCA 80:-1.1 CCA 81:+0.5 CCA 82:-1.1 CCA 83:+0.5 CCA 84:-1.1
Step 9: Verify that the calibration constants you entered were correctly received, by entering the following query commands:
CCA? 80 CCA? 81 CCA? 82 CCA? 83 CCA? 84
Observe that the correct calibration constants are reported.

11A81 Service Reference

	Perform the Procedures 1 through 3 in the <i>Checks and Adjustments</i> f this manual.
Step 11:	Set the ON/STANDBY switch to STANDBY.
Step 12:	Remove the amplifier.
•	Return the jumpers J1630 on the 11A81 Main board and J450 on

Multi-Pin Connectors

Pin 1 on a multi-pin connector is designated with a triangle (or arrowhead) on the holder. A square pad on the board denotes pin 1. When a connection is made to a board, the square pad determines the indexing of the symbol on the multi-pin holder.

A gap between the pin 1 and 3 positions in the holder keys a multi-pin connector. There is a corresponding gap between pins 1 and 3 on the board. (A small plastic plug covers the pin 2 position on the end of the holder.)

Align the plastic plug of the holder with the gap between the board pins (see Figure 3-12).

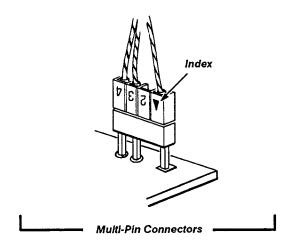


Figure 3-12 — Multi-Pin Connector Orientation

3-38 Corrective Maintenance

Theory of Operation

The Tektronix 11A81 Amplifier is a wide bandwidth single-channel amplifier that operates only in 11403A and 11404 oscilloscope mainframes.

System Functional Overview

This section describes and illustrates (see Figure 4-1) the major functional blocks of the 11A81 Amplifier

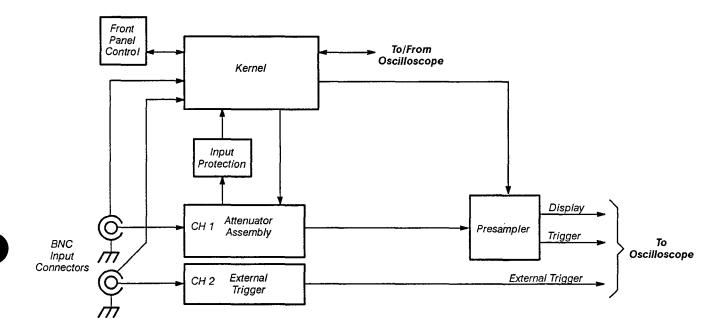


Figure 4-1 — 11A81 Amplifier System Functional Block Diagram

Attenuator Assembly Block

The Attenuator assembly contains ganged attenuators that scale or attenuate the input signal.

Input Protection Block

The Input Protection block protects the Presampler from both steady voltage levels in excess of 5 V rms and signal spikes.

Presampler Block

The Presampler block provides amplification and offset of the input signal. The Presampler block produces two output signals: a display signal and a trigger signal. Each of these signals can be independently inverted or switched off.

11A81 Service Reference 4-1

Front Panel Control Block

The Front Panel Control block provides information on the status of the front panel buttons to the Kernel block.

Kernel Block

The Kernel block has the following major functions:

- to monitor the front panel button and probe information (such as type and attenuation)
- to interpret commands from the oscilloscope and then set the appropriate signal path configuration
- to manage the amplifier diagnostics and calibration
- control CH 1 coupling/disconnect

External Trigger Block

The External Trigger block contains the trigger circuit for the 2 GHz trigger path. The Kernel block sets the trigger level and slope for the trigger circuit. A relay selects either the External Trigger or the internal trigger derived from the CH 1 input.

Typical Signal Processing Cycle

The following sequence is a brief overview of how the amplifier acquires and processes a signal from the input connector:

- 1. An analog input signal is connected to the CH 1 BNC input connector.
- 2. The Cal Relay sets the input coupling mode (DC or Off) and the attenuator assembly scales the input signal prior to amplification.
- The Presampler block samples the CH 1 input when strobed by the mainframe. This analog sample is briefly held for the mainframe to digitize. The internal trigger, which is derived from the CH 1 signal, is bandwidth limited.
- 4. At every acquisition strobe from the mainframe digitizer, the input signal is sampled again. This continues until the mainframe halts acquisition.
- The Kernel block sets the offset voltage for the Presampler block. The Presampler subtracts the offset voltage from the attenuated signal and then amplifies and samples the resultant signal.
- 6. The Kernel block provides Normal/Invert control signals to the amplifier display and trigger paths, and on/off control for input protection.
- 7. The Diode Bridge circuit ensures that a high-voltage spike does not damage the Presampler and the 5 V Overload RMS Sense circuit detects sustained overdrive and decouples the input with the Cal Relay.
- 8. The External Trigger block generates a trigger-received signal to the mainframe when an applied signal has the required slope and trigger level. Slope (+ or -) and trigger level settings are controlled by the MPU.

11A81 Service Reference 4-3

Detailed Block Diagram Descriptions

This section describes and illustrates the 11A81 Amplifier block diagram (see Figure 4-2).

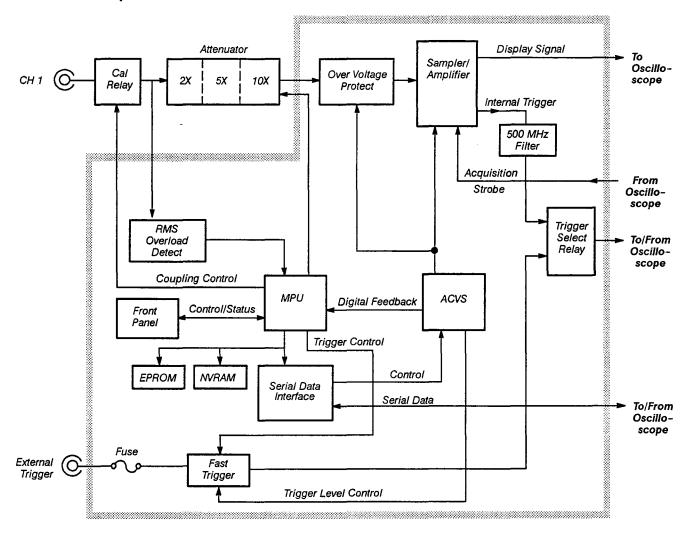


Figure 4-2 — 11A81 Amplifier Detailed Block Diagram

Cal Relay

The Cal Relay provides for calibration of the input channel and for an Off coupling mode. The Off coupling mode is selected automatically when an an excessive input signal is detected by the RMS pickoff circuit. The input coupling mode can be set to DC or off.

During calibration and Self-Tests, the Cal Relay connects a calibration reference signal, from the mainframe, to the attenuator. During these operations, the CH 1 input is disconnected from the attenuator.

RMS Overload Detect

The RMS Overload Detect circuit senses an overvoltage condition (greater than $\pm\,5$ V rms) and disconnects the CH 1 input. The MPU receives an overvoltage signal then switches the Cal Relay to Off coupling. The RMS Overload circuit consists of a signal pickoff board in the input SMA line, a sense semi-connector

Attenuator Block

The Attenuator block provides attenuation of the input signal to scale the signal to within the acceptable range of the Presampler. The attenuator is implemented as three cascaded sections: 2X, 5X, and 10X. Each or all of the attenuators can be switched in to produce the desired vertical size settings. The Attenuator block must be replaced as a unit.

A1 Main Board

The A1 Main board consists of:

- Presampler
- strobe delay lines
- Microprocessor Unit (MPU)
- EPROMIC
- NVRAM IC
- Serial Data Interface (SDI)
- Analog Control Voltage System (ACVS)

The Presampler — amplifies the difference between the input signal and the DC offset voltage. The amplified signal is held briefly by the sampler for digitizing by the mainframe when strobed by the mainframe acquisition strobe. The input analog signal is picked off and fed through and bandwidth limited to provide the internal trigger.

The Fast Trigger — circuit monitors the External Trigger signal. A fuse protects the Fast Trigger circuit from input signals outside the ± 1 range. The ACVS system and the MPU control the trigger level and slope settings, respectively.

The Trigger Relay — selects either the External Trigger or the internal trigger derived from the CH 1 input signal.

The MPU — receives setting information from the oscilloscope and then implements these settings in the amplifier. It monitors the Front Panel and the RMS Overload Detect block. It controls settings in the Cal Relay, the Fast Trigger circuit, and the ACVS block.

The EPROM IC — stores the program code. The MPU uses this code to execute its functions.

11A81 Service Reference 4-5

The NVRAM IC — stores information; such as, the amplifier calibration constants, the amplifier serial number, and probe calibration constants.

The Serial Data Interface (SDI) IC — manages ACVS system with its array of sample and hold circuits to create eight analog control voltages. The SDI IC performs these functions on commands from the MPU. The MPU also stores the channel switching sequence in the SDI IC.

The SDI IC contains a receiver and transmitter for serial communications between the amplifier and oscilloscope. The SDI IC converts eight-bit data bytes from the MPU into a serial data signal. This signal is then sent to the oscilloscope. Conversely, the SDI IC converts the serial data from the oscilloscope into eight-bit data bytes for the MPU to read.

The ACVS — generates analog control voltages under control of the SDI IC and MPU. These control voltages provide biasing for the signal path components, offset for the Presampler, and trigger level for the trigger circuits.

A2 Front Panel Board

The A2 Front Panel board contains an LED and a push button. The oscilloscope software will turn on the LED when its corresponding push button is pressed.

Replaceable Parts

This section contains the list of replaceable components for the 11A81 Amplifier. As described below, use this list to identify and order replacement parts. Figure 5-1, at the rear of this section provides an exploded view of all replaceable components.

Parts Ordering Information

Replacement parts are available from or through your local Tektronix, Inc., service center or representative.

Changes to Tektronix instruments are sometimes made to accommodate improved components as they become available and to give you the benefit of the latest circuit improvements. Therefore, when ordering parts, it is important to include the following information in your order:

- Part number
- Instrument type or model number
- Instrument serial number
- Instrument modification number, if applicable

If a part you order has been replaced with a different or improved part, your local Tektronix service center or representative will contact you concerning any change in the part number.

Module Replacement

The 11A81 is serviced by module replacement; there are three options you should consider:

- Module Exchange. In some cases you may exchange your module for a remanufactured module. These modules cost significantly less than new modules and meet the same factory specifications. For more information about the module exchange program, call 1-800-TEKWIDE, ext. BVJ5799.
- Module Repair. You may ship your module to us for repair, after which we will return it to you.
- New Modules. You may purchase new, replacement modules in the same way as other replacement parts.

11A81 Service Reference 5-1

Using the Replaceable Parts List

The tabular information in the Replaceable Parts List is arranged for quick retrieval. Understanding the structure and features of the list will help you find the all the information you need for ordering replacement parts.

Item Names

In the Replaceable Parts List, an Item Name is separated from the description by a colon (:). Because of space limitations, an Item Name may sometimes appear as incomplete. For further Item Name identification, use the U.S. Federal Cataloging Handbook H6-1, where available.

Indentation System

Indentation in this parts list shows the relationship between items. The following is an example of the indentation system used in the Description column:

1 2 3 4 5

Name & Description

Assembly and/or Component
Attaching parts for Assembly and/or Component

(END ATTACHING PARTS)

Detail Part of Assembly and/or Component Attaching parts for Detail Part

(END ATTACHING PARTS)

Parts of Detail Part
Attaching parts for Parts of Detail Part
(END ATTACHING PARTS)

Attaching parts always appear at the same indentation as the item it mounts, while the detail parts are indented to the right. Indented items are part of, and included with, the next higher indentation. Attaching parts must be purchased separately, unless otherwise specified.

Abbreviations

Abbreviations conform to American National Standards Institute (ANSI) standard Y1.1

CROSS INDEX - MFR. CODE NUMBER TO MANUFACTURER

Mfr. Code	Manufacturer	Address	City, State, Zip Code
TK1163	POLYCAST INC	9898 SW TIGARD ST	TIGARD OR 97223
TK1326	NORTHWEST FOURSLIDE INC	18224 SW 100TH CT	TUALATIN OR 97062
TK1465	BEAVERTON PARTS MFG CO	1800 NW 216TH AVE	HILLSBORO OR 97124-6629
TK1967	SYNDETEK	3915 E MAIN	SPOKANE WA 99202
TK2197	E-Z FORM CABLE CORP	441 CHAPEL ST PO BOX 9442	NEW HAVEN CT 06534
TK2338	ACC MATERIALS	ED SNYDER BLDG 38-302	BEAVERTON OR 97077
TK2469	UNITREK CORPORATION	3000 LEWIS & CLARK WAY SUITE #2	VANCOUVER WA 98601
0B0A9	DALLAS SEMICONDUCTOR CORP	4350 BELTWOOD PKWY SOUTH	DALLAS TX 75244
0JR05	TRIQUEST CORP	3000 LEWIS AND CLARK HWY	VANCOUVER WA 98661-2999
0J9P9	GEROME MFG CO INC	PO BOX 737	NEWBURG OR 97132
0KB01	STAUFFER SUPPLY	810 SE SHERMAN	PORTLAND OR 97214
07416	NELSON NAME PLATE CO	3191 CASITAS	LOS ANGELES CA 90039-2410
09922	BURNDY CORP	RICHARDS AVE	NORWALK CT 06852
22526	DU PONT E I DE NEMOURS AND CO INC DU PONT ELECTRONICS DEPT	515 FISHING CREEK RD	NEW CUMBERLAND PA 17070-3007
22599	AMERACE CORP ESNA DIV	15201 BURBANK BLVD SUITE C	VAN NUYS CA 91411-3532
50667	DYNATECH MICROWAVE TECHNOLOGY INC DYNATECH MICROWAVE SWITCHES DIV	26655 W AGOURA RD	CLABASAS CA 91302-1921
53387	MINNESOTA MINING MFG CO	PO BOX 2963	AUSTIN TX 78769-2963
66302	VLSI TECHNOLOGY INC	1109 MCKAY DR	SAN JOSE CA 95131-1706
8X345	NORTHWEST SPRING & MFG CO	5858 WILLOW LANE	LAKE OSWEGO OR 97034-5343
80009	TEKTRONIX INC	14150 SW KARL BRAUN DR PO BOX 500	BEAVERTON OR 97077-0001
83385	MICRODOT MFG INC GREER-CENTRAL DIV	3221 W BIG BEAVER RD	TROY MI 48098
83486	ELCO INDUSTRIES INC	1101 SAMUELSON RD	ROCKFORD IL 61101
92101	SCHULZE MFG	50 INGOLD RD	BURLINGAME CA 94010-2206
93907	TEXTRON INC CAMCAR DIV	600 18TH AVE	ROCKFORD IL 61108-5181

11A81 Service Reference 5-3

Scan by Zenith

Fig. & Index No.	Tektronix Part No.	Serial No. Effective Dscont	Qty	12345 Name & Description	Mfr. Code	Mfr. Part No.
1 -1	214-1061-00		1	CONTACT, ELEC: GROUNDING, CU BE	80009	214106100
-2	426-2435-00		1	FRAME, SECT: PLUG-IN, UPPER, ALUMINUM	TK1465	ORDER BY DESC
-3	211-0392-00		10	SCREW,MACHINE:4-40 X 0.25,FLH,82 DEG,STL	93907	ORDER BY DESC
-4	174-2606-00		1	CABLE ASSY,RF:COAX,11.75 L,6-N	80009	174260600
-5	174-2584-00		1	CABLE ASSY,RF:50 OHM COAX,23.0 L,6-N	80009	174258400
-6	211-0391-00		4	SCREW,MACHINE:2-56 X 0.437,P4,STL,T8	83486	ORDER BY DESC
-7	211-0409-00		4	SCR,ASSEM WSHR:4-40 X 0.312,PNH,STL,T10	93907	829-06888-024
-8	407-3918-00		1	BRACKET, ANGLE: ATTENUATOR, ALUMINUM	80009	407391800
-9	119-4086-00		1	ATTEN,PRGM:50 OHM,DC-56HZ,SEL	80009	119-4086-00
-10	165-2448-00		1	MICROCKT,LIN:DIODE BRDG,1.75CM HYPCONS (A1U950)	80009	165244800
-11	119-3690-00		1	HYPCON ASSY:44 CONTACT,STEP MOUNT	TK2338	ORDER BY DESC
-12	136-0813-00		3	SKT,PL-IN ELEK:CHIP CARRIER,68 CONTACTS	53387	268-5400-00-110
-13	211-0409-00		2	SCR,ASSEM WSHR:4-40 X 0.312,PNH,STL,T10	93907	829-06888-024
-14	211-0411-00		4	SCR,ASSEM WSHR:4-40 X 0.5,PNH,STL,T10	93907	ORDER BY DESC
-15	119-3689-00		1	HYPCON ASSY:64 CONTACT, FLUSH MOUNT	TK2338	ORDER BY DESC
-16	165-2392-00		1	MICROCKT,LINEAR:PRE SAMPLER,H2392 (A1U650)	80009	165239200
	006-2655-00		1	THRM JT CMPD:#249 THERMALLOY	80009	006265500
-17	344-0248-00		2	CLIP,FUSE:0.866 L,CU BE	80009	344024800
-18	159-0118-00		2	FUSE,THERMAL:50 OHM (A1F330 & SPARE)	80009	159011800
-19	213-0904-00		4	SCREW,TPG,TR:6-32 X 0.5,PNH,STL	83385	ORDER BY DESC
-20	386-5296-00		1	PANEL, REAR: POLYCARBONATE	TK1163	ORDER BY DESC
-21	671-1621-00		1	CIRCUIT BD ASSY:MAIN (A1)	80009	671162100
-22	407-4089-00		1	BRACKET,HT SK:ALUMINUM	0J9P9	ORDER BY DESC
-23	211-0409-00		10	SCR, ASSEM WSHR:4-40 X 0.312, PNH, STL, T10	93907	829-06888-024
-24	214-4426-00		1	BLOCK,HEAT SINK:ALUMINUM	TK1465	ORDER BY DESC
-25	220-0022-00		2	NUT BLOCK:0.4 X 0.25 X 0.33,4-40 THRU,NI	80009	220002200
-26	131-4258-00		1	CONN,RCPT,ELEC:COAX,PELTOLA END,BE-CU (A1J1050)	TK1326	ORDER BY DESC
-27	174-2453-00		1	CABLE ASSY,RF:50 OHM COAX,10.0 L,6-N	TK2469	ORDER BY DESC
-28	211-0100-00		2	SCREW,MACHINE:2-56 X 0.750,PNH,STL,POZ	83385	ORDER BY DESC
-29	119-1161-01		1	SW,RF XMSN LINE:DC TO 21GHZ,60 DB ISOL	50667	D3-412C002
-30	174-2426-00		1	CABLE ASSY,RF:50 OHM COAX,1.398 L	TK2197	ORDER BY DESC
-31	426-2061-00		1	FR SECT,PLUG-IN:LOWER,ALUMINUM	TK1465	ORDER BY DESC
-32	337-1064-11		2	SHIELD, ELEC: PLUG-IN SIDE	80009	ORDER BY DESC
-33	671-2171-00		1	CIRCUIT BD ASSY:RMS PICKOFF (A3)	80009	671217100
-34	407-4090-00		1	BRACKET, RELAY: ALUMINUM	0J9P9	ORDER BY DESC
-35	131-3589-03		2	CONN ASSY,ELEC:FRONT PANEL	80009	131358903
-36	354-0654-00		2	RING,CONN ALIGN:BNC	0JR05	ORDER BY DESC
-37	211-0413-00		10	SCREW,MACHINE:2-56 X 0.375,FLH,82 DEG,STL	93907	221-00995-024
-38	105-0076-04		1	RELEASE BAR, LCH: PLUG-IN UNIT	0JR05	ORDER BY DESC
-39	366-0600-00		1	PUSH BUTTON:0.269 X 0.409,ABS	TK1163	ORDER BY DESC
-40	214-1095-00		1	PIN,SPRING:0.187 L X 0.094 OD,STL	22599	52-022-094-0187
-41	214-1054-00		1	SPRING,FLAT:0.825 X 0.322,SST	TK1326	ORDER BY DESC
-42	105-0075-00		1	BOLT, LATCH: 7A & 7B SER PL-IN	80009	105007500
-43 -44	214-1280-00		1	SPRING, HLCPS: 0.14 OD X 1.126 L, TWIST LOOP	8X345	ORDER BY DESC
-44	366-1058-00		1	KNOB:GRAY,0.625 X 0.255 X 0.485	0JR05	ORDER BY DESC

Scan by Zenith

Fig. & Index No.	Tektronix Part No.	Serial No. Effective Dscont	Qty	12345 Name & Description	Mfr. Code	Mfr. Part No.
1 -45	348-0235-00		2	SHLD GSKT,ELEK:FINGER TYPE,4.734 L	92101	ORDER BY DESC
-46	333-3865-00		1	PANEL, FRONT: 11A81, MODULE	07416	ORDER BY DESC
-47	386-5219-00		1	SUBPANEL, FRONT:	TK1465	ORDER BY DESC
-48	670-9336-00		1	CIRCUIT BD ASSY:FRONT PANEL (A2)	80009	670933600
-49	174-0159-00		1	CA ASSY,SP,ELEC:6,26 AWG,3.0 L,RIBBON	TK1967	ORDER BY DESC
-50	131-0993-00		3	BUS,CONDUCTOR:SHUNT/SHORTING (A1J1630,A1J1970, & A1J2180)	22526	65474-006
-51	156-2625-00		1	MICROCKT,DGTL:NMOS,CUSTOM (A1U1540)	66302	VF4124RC CC0001
-52	670-8986-00		2	CIRCUIT BD ASSY:SAMPLE/HOLD (A1A1 & A1A2)	80009	670898600
-53	160-8195-00		1	MICROCKT.DGTL:CMOS,16 X 8 EPROM (A1U2140)	80009	160819500
-54	136-0755-00		1	SOCKET.DIP::PCB.:28 POS.2 X 14.0.1 X 0.6 CTR	09922	DILB28P-108
-55	156-2671-00		1	IC,MEMORY:CMOS,NVRAM;2K X 8,200NS (A1U2040)	0B0A9	DS1220Y
-56	220-0182-00		1	PLATE,NUT:0.063 AL	0J9P9	ORDER BY DESC
				ACCESSORIES		
	070-8147-00		1	MANUAL,TECH:USER REFERENCE,11A81	80009	070814700
	070-8148-00		1	MANUAL, TECH: SERVICE REFERENCE, 11A81	80009	070814800

11A81 Service Reference 5-5

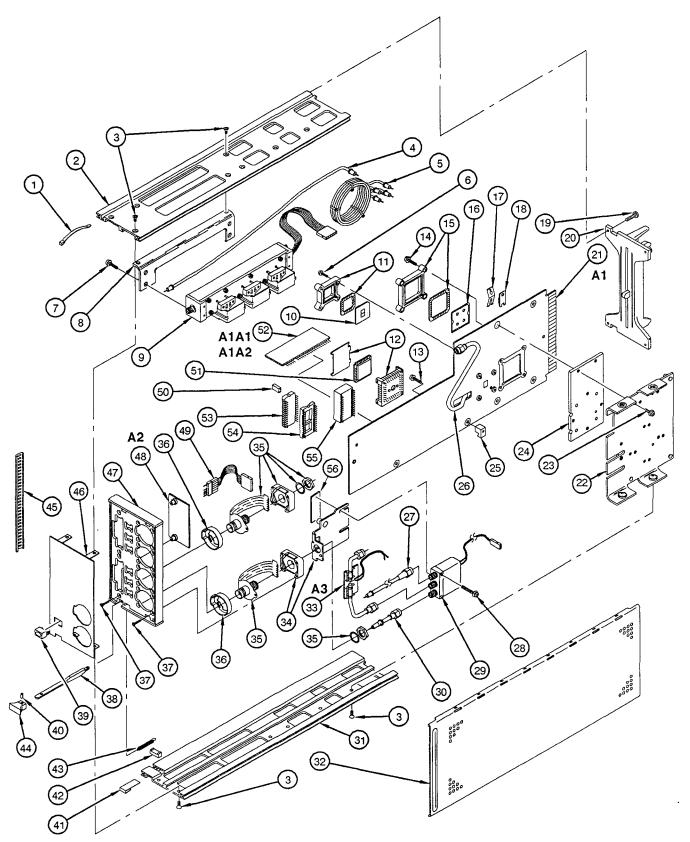


Figure 5-1 - Exploded View of the 11A81 Amplifier